

# 具有 70V 总线故障保护功能和灵活数据速率的 ISO1042-Q1 汽车隔离式 CAN 收发器

## 1 特性

- AEC Q100 标准：符合汽车应用要求
- 1 级：-40°C 至 +125°C 环境温度
- 提供功能安全
  - 可提供用于功能安全系统设计的文档
- 符合 ISO 11898-2:2016 物理层标准
- 支持经典的最高 1Mbps CAN 和最高 5Mbps FD (灵活数据速率)
- 低环路延迟：152ns
- 保护特性
  - 直流总线故障保护电压： $\pm 70V$
  - 总线引脚的 HBM ESD 容差： $\pm 16kV$
  - 驱动器显性超时 (TXD DTO)
  - $V_{CC1}$  和  $V_{CC2}$  欠压保护
- 共模电压范围： $\pm 30V$
- 未上电时的理想无源、高阻抗总线终端
- 高 CMTI：100kV/ $\mu s$
- $V_{CC1}$  电压范围：1.71V 至 5.5V
  - 支持连接到 CAN 控制器的 1.8V、2.5V、3.3V 和 5.0V 逻辑接口
- $V_{CC2}$  电压范围：4.5V 至 5.5V
- 优异的电磁兼容性 (EMC)
  - 系统级 ESD、EFT 和浪涌抗扰性
  - 低辐射
- 16-SOIC 和 8-SOIC 封装选项
- 提供工业版本：[ISO1042](#)
- 安全相关认证：
  - 符合 DIN VDE V 0884-11:2017-01 标准的 7071V<sub>PK</sub>  $V_{IOTM}$  和 1500V<sub>PK</sub>  $V_{IORM}$  (增强型和基本型选项)
  - UL 1577 标准下，长达 1 分钟的 5000V<sub>RMS</sub> 隔离
  - CQC、TUV 和 CSA 认证

## 2 应用

- 起动机/发电机
- 电池管理系统 (BMS)
- 直流/直流转换器
- 车载充电器 (OBC) 和无线充电器
- 逆变器和电机控制

## 3 说明

ISO1042-Q1 器件是一款符合 ISO11898-2 (2016) 标准规格的电隔离控制器局域网 (CAN) 收发器。ISO1042-Q1 器件提供  $\pm 70V$  直流母线故障保护功能和  $\pm 30V$  共模电压范围。该器件在 CAN FD 模式下最高支持

5Mbps 数据速率，与经典 CAN 相比可实现更为快速的载荷传输。该器件采用二氧化硅 (SiO<sub>2</sub>) 绝缘栅，可承受 5000V<sub>RMS</sub> 的电压和 1060V<sub>RMS</sub> 的工作电压。电磁兼容性得到了显著增强，可实现系统级 ESD、EFT 和浪涌并符合辐射标准。与隔离式电源一起使用，此器件可抵御高电压冲击，并防止总线的噪声电流进入本地接地。ISO1042-Q1 器件提供基础型和增强型隔离 (请参阅 [增强型和基础型隔离选项](#))。ISO1042-Q1 器件支持 -40°C 至 +125°C 的宽环境温度范围，该器件采用 SOIC-16 (DW) 封装和较小的 SOIC-8 (DWV) 封装。

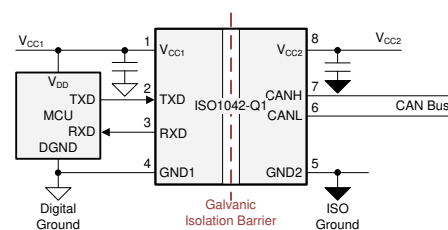
### 器件信息

器件型号 <sup>(1)</sup>	封装	封装尺寸 (标称值)
ISO1042-Q1	SOIC (8)	5.85mm × 7.50mm
	SOIC (16)	10.30mm × 7.50mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

### 增强型和基础型隔离选项

特性	ISO1042x-Q1	ISO1042Bx-Q1
保护级别	增强型	基本型
浪涌测试电压	10000V <sub>PK</sub>	6000V <sub>PK</sub>
隔离额定值	5000V <sub>RMS</sub>	5000V <sub>RMS</sub>
工作电压	1060V <sub>RMS</sub> / 1500V <sub>PK</sub>	1060V <sub>RMS</sub> / 1500V <sub>PK</sub>



应用示意图

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## 4 Revision History

注：以前版本的页码可能与当前版本的页码不同

<b>Changes from Revision A (January 2020) to Revision B (October 2020)</b>	<b>Page</b>
• 添加了“功能安全”要点.....	1

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<b>Changes from Revision * (October 2018) to Revision A (January 2020)</b>	<b>Page</b>
• 更改了新的安全认证.....	1

## 5 Pin Configuration and Functions

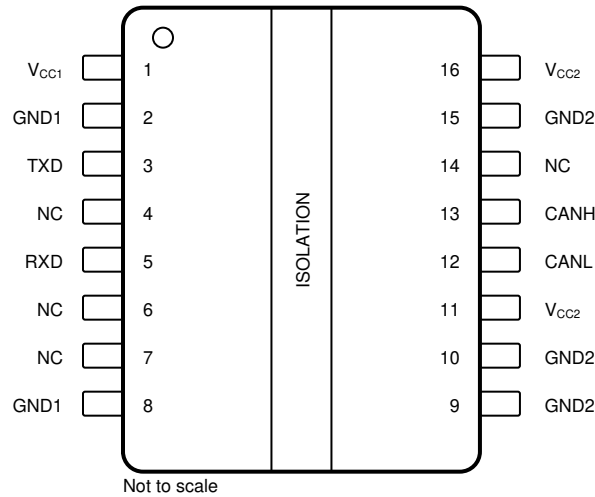


图 5-1. DW Package 16-Pin SOIC Top View

表 5-1. Pin Functions—16 Pins

PIN		I/O	DESCRIPTION
NO.	NAME		
1	V <sub>CC1</sub>	—	Digital-side supply voltage, Side 1
2	GND1	—	Digital-side ground connection, Side 1
3	TXD	I	CAN transmit data input (LOW for dominant and HIGH for recessive bus states)
4	NC	—	Not connected
5	RXD	O	CAN receive data output (LOW for dominant and HIGH for recessive bus states)
6	NC	—	Not connected
7	NC	—	Not connected
8	GND1	—	Digital-side ground connection, Side 1
9	GND2	—	Transceiver-side ground connection, Side 2
10			
11	V <sub>CC2</sub>	—	Transceiver-side supply voltage, Side 2. Must be externally connected to pin 16.
12	CANL	I/O	Low-level CAN bus line
13	CANH	I/O	High-level CAN bus line
14	NC	—	Not connected
15	GND2	—	Transceiver-side ground connection, Side 2
16	V <sub>CC2</sub>	—	Transceiver-side supply voltage, Side 2. Must be externally connected to pin 11.

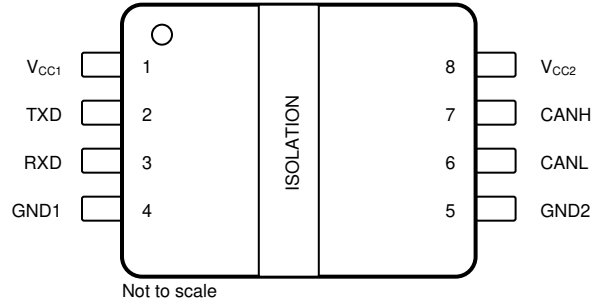


图 5-2. DWV Package 8-Pin SOIC Top View

表 5-2. Pin Functions—8 Pins

PIN		I/O	DESCRIPTION
NO.	NAME		
1	V <sub>CC1</sub>	—	Digital-side supply voltage, Side 1
2	TXD	I	CAN transmit data input (LOW for dominant and HIGH for recessive bus states)
3	RXD	O	CAN receive data output (LOW for dominant and HIGH for recessive bus states)
4	GND1	—	Digital-side ground connection, Side 1
5	GND2	—	Transceiver-side ground connection, Side 2
6	CANL	I/O	Low-level CAN bus line
7	CANH	I/O	High-level CAN bus line
8	V <sub>CC2</sub>	—	Transceiver-side supply voltage, Side 2

## 6 Specifications

### 6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)<sup>(1) (2)</sup>

		MIN	MAX	UNIT
V <sub>CC1</sub>	Supply voltage, side 1	-0.5	6	V
V <sub>CC2</sub>	Supply voltage, side 2	-0.5	6	V
V <sub>IO</sub>	Logic input and output voltage range (TXD and RXD)	-0.5	V <sub>CC1</sub> +0.5 <sup>(3)</sup>	V
I <sub>O</sub>	Output current on RXD pin	-15	15	mA
V <sub>BUS</sub>	Voltage on bus pins (CANH, CANL)	-70	70	V
V <sub>BUS_DIFF</sub>	Differential voltage on bus pins (CANH-CANL)	-70	70	V
T <sub>J</sub>	Junction temperature	-40	150	°C
T <sub>STG</sub>	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values except differential I/O bus voltages are with respect to the local ground terminal (GND1 or GND2) and are peak voltage values.
- (3) Maximum voltage must not exceed 6 V

### 6.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge Human body model (HBM), per ANSI/ ESDA/JEDEC JS-001	All pins <sup>(1)</sup>	±6000	V
		CANH and CANL to GND2 <sup>(1)</sup>	±16000	V
	Electrostatic discharge Charged device model (CDM), per JEDEC specification JESD22-C101	All pins <sup>(2)</sup>	±1500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Transient Immunity

	PARAMETER	TEST CONDITIONS	VALUE	UNIT
V <sub>PULSE</sub>	ISO7637-2 Transients according to GIFT - ICT CAN EMC test specification	Pulse 1; CAN bus terminals (CANH, CANL) to GND2	-100	V
		Pulse 2; CAN bus terminals (CANH, CANL) to GND2	75	V
		Pulse 3a; CAN bus terminals (CANH, CANL) to GND2	-150	V
		Pulse 3b; CAN bus terminals (CANH, CANL) to GND2	100	V

### 6.4 Recommended Operating Conditions

		MIN	MAX	UNIT
V <sub>CC1</sub>	Supply Voltage, Side 1, 1.8-V operation	1.71	1.89	V
	Supply Voltage, Side 1, 2.5-V, 3.3-V and 5.5-V operation	2.25	5.5	V
V <sub>CC2</sub>	Supply Voltage, Side 2	4.5	5.5	V
T <sub>A</sub>	Operating ambient temperature	-40	125	°C

## 6.5 Thermal Information

THERMAL METRIC <sup>(1)</sup>		ISO1042-Q1		UNIT
		DW (SOIC)	DWV (SOIC)	
		16 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	69.9	100	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	31.8	40.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	29.0	51.8	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	13.2	16.8	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	28.6	49.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	-	-	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.6 Power Ratings

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$P_D$	Maximum power dissipation (both sides)	See <a href="#">Figure 7-3</a> , $V_{CC1} = V_{CC2} = 5.5\text{ V}$ , $T_J = 150^\circ\text{C}$ , $R_L = 50\ \Omega$ , A repetitive pattern on TXD with 1 ms time period, 990 $\mu\text{s}$ LOW time, and 10 $\mu\text{s}$ HIGH time.			385	mW
$P_{D1}$	Maximum power dissipation (side-1)	See <a href="#">Figure 7-5</a> , $V_{CC1} = V_{CC2} = 5.5\text{ V}$ , $T_J = 150^\circ\text{C}$ , $R_L = 50\ \Omega$ , Input a 2-V pk-pk 2.5-MHz 50% duty cycle differential square wave on CANH-CANL			25	mW
$P_{D2}$	Maximum power dissipation (side-2)	See <a href="#">Figure 7-3</a> , $V_{CC1} = V_{CC2} = 5.5\text{ V}$ , $T_J = 150^\circ\text{C}$ , $R_L = 50\ \Omega$ , A repetitive pattern on TXD with 1 ms time period, 990 $\mu\text{s}$ LOW time, and 10 $\mu\text{s}$ HIGH time.			360	mW

## 6.7 Insulation Specifications

PARAMETER		TEST CONDITIONS	SPECIFICATIONS		UNIT
			DW-16	DWV-8	
<b>IEC 60664-1</b>					
CLR	External clearance <sup>(1)</sup>	Side 1 to side 2 distance through air	>8	>8.5	mm
CPG	External Creepage <sup>(1)</sup>	Side 1 to side 2 distance across package surface	>8	>8.5	mm
DTI	Distance through the insulation	Minimum internal gap (internal clearance)	>17	>17	μm
CTI	Comparative tracking index	IEC 60112; UL 746A	>600	>600	V
	Material Group	According to IEC 60664-1	I	I	
	Overvoltage category	Rated mains voltage ≤ 600 V <sub>RMS</sub>	I-IV	I-IV	
		Rated mains voltage ≤ 1000 V <sub>RMS</sub>	I-III	I-III	
<b>DIN VDE V 0884-11:2017-01<sup>(2)</sup></b>					
V <sub>IORM</sub>	Maximum repetitive peak isolation voltage	AC voltage (bipolar)	1500	1500	V <sub>PK</sub>
V <sub>IOWM</sub>	Maximum isolation working voltage	AC voltage (sine wave); time-dependent dielectric breakdown (TDDb) test;	1060	1060	V <sub>RMS</sub>
		DC voltage	1500	1500	V <sub>DC</sub>
V <sub>IOTM</sub>	Maximum transient isolation voltage	V <sub>TEST</sub> = V <sub>IOTM</sub> , t = 60 s (qualification); V <sub>TEST</sub> = 1.2 × V <sub>IOTM</sub> , t = 1 s (100% production)	7071	7071	V <sub>PK</sub>
V <sub>IOSM</sub>	Maximum surge isolation voltage ISO1042-Q1 <sup>(3)</sup>	Test method per IEC 62368-1, 1.2/50 μs waveform, V <sub>TEST</sub> = 1.6 × V <sub>IOSM</sub> = 10000 V <sub>PK</sub> (qualification)	6250	6250	V <sub>PK</sub>
	Maximum surge isolation voltage ISO1042B-Q1 <sup>(3)</sup>	Test method per IEC 62368-1, 1.2/50 μs waveform, V <sub>TEST</sub> = 1.3 × V <sub>IOSM</sub> = 6000 V <sub>PK</sub> (qualification)	4615	4615	V <sub>PK</sub>
q <sub>pd</sub>	Apparent charge <sup>(4)</sup>	Method a: After I/O safety test subgroup 2/3, V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 60 s; V <sub>pd(m)</sub> = 1.2 × V <sub>IORM</sub> , t <sub>m</sub> = 10 s	≤ 5	≤ 5	pC
		Method a: After environmental tests subgroup 1, V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 60 s; ISO1042-Q1: V <sub>pd(m)</sub> = 1.6 × V <sub>IORM</sub> , t <sub>m</sub> = 10 s; ISO1042B-Q1: V <sub>pd(m)</sub> = 1.2 × V <sub>IORM</sub> , t <sub>m</sub> = 10 s	≤ 5	≤ 5	
		Method b1: At routine test (100% production) and preconditioning (type test), V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 1 s; ISO1042-Q1: V <sub>pd(m)</sub> = 1.875 × V <sub>IORM</sub> , t <sub>m</sub> = 1 s; ISO1042B-Q1: V <sub>pd(m)</sub> = 1.5 × V <sub>IORM</sub> , t <sub>m</sub> = 1 s	≤ 5	≤ 5	
C <sub>IO</sub>	Barrier capacitance, input to output <sup>(5)</sup>	V <sub>IO</sub> = 0.4 × sin(2πft), f = 1 MHz	1	1	pF
R <sub>IO</sub>	Insulation resistance, input to output <sup>(5)</sup>	V <sub>IO</sub> = 500 V, T <sub>A</sub> = 25°C	> 10 <sup>12</sup>	> 10 <sup>12</sup>	Ω
		V <sub>IO</sub> = 500 V, 100°C ≤ T <sub>A</sub> ≤ 150°C	> 10 <sup>11</sup>	> 10 <sup>11</sup>	
		V <sub>IO</sub> = 500 V at T <sub>S</sub> = 150°C	> 10 <sup>9</sup>	> 10 <sup>9</sup>	
	Pollution degree		2	2	
	Climatic category		40/125/21	40/125/21	
<b>UL 1577</b>					
V <sub>ISO</sub>	Withstand isolation voltage	V <sub>TEST</sub> = V <sub>ISO</sub> , t = 60 s (qualification); V <sub>TEST</sub> = 1.2 × V <sub>ISO</sub> , t = 1 s (100% production)	5000	5000	V <sub>RMS</sub>

- (1) Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance. Creepage and clearance on a printed-circuit board become equal in certain cases. Techniques such as inserting grooves, ribs, or both on a printed circuit board are used to help increase these specifications.

**ISO1042-Q1**

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- (2) ISO1042-Q1 is suitable for *safe electrical insulation* and ISO1042B-Q1 is suitable for *basic electrical insulation* only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.
- (3) Testing is carried out in air or oil to determine the intrinsic surge immunity of the isolation barrier.
- (4) Apparent charge is electrical discharge caused by a partial discharge (pd).
- (5) All pins on each side of the barrier tied together creating a two-pin device.

## 6.8 Safety-Related Certifications

VDE	CSA	UL	CQC	TUV
Certified according to DIN VDE V 0884-11:2017- 01	Certified according to IEC 60950-1, IEC 62368-1 and IEC 60601-1	Recognized under UL 1577 Component Recognition Program	Certified according to GB4943.1-2011	Certified according to EN 61010-1:2010/A1:2019, EN 60950-1:2006/A2:2013 and EN 62368-1:2014
Maximum transient isolation voltage, 7071 V <sub>PK</sub> ; Maximum repetitive peak isolation voltage, 1500 V <sub>PK</sub> ; Maximum surge isolation voltage, ISO1042-Q1: 6250 V <sub>PK</sub> (Reinforced) ISO1042B-Q1: 4615 V <sub>PK</sub> (Basic)	CSA 60950-1-07+A1+A2, IEC 60950-1 2 <sup>nd</sup> Ed.+A1+A2 and IEC 62368-1 2 <sup>nd</sup> Ed., for pollution degree 2, material group I ISO1042-Q1: 800 V <sub>RMS</sub> reinforced isolation ISO1042B-Q1: 1060 V <sub>RMS</sub> basic isolation ----- CSA 60601- 1:14 and IEC 60601-1 Ed. 3.1+A1, ISO1042-Q1: 2 MOPP (Means of Patient Protection) 250 V <sub>RMS</sub> (354 V <sub>PK</sub> ) maximum working voltage	Single protection, 5000 V <sub>RMS</sub>	Reinforced insulation, Altitude ≤ 5000 m, Tropical Climate, 700 V <sub>RMS</sub> maximum working voltage	EN 61010-1:2010 / A1:2019 ISO1042-Q1: 600 V <sub>RMS</sub> reinforced isolation ISO1042B-Q1: 1000 V <sub>RMS</sub> basic isolation ----- EN 60950-1:2006/A2:2013 and EN 62368-1:2014 ISO1042-Q1: 800 V <sub>RMS</sub> reinforced isolation ISO1042B-Q1: 1060 V <sub>RMS</sub> basic isolation
Certificates: Reinforced: 40040142 Basic: 40047657	Master contract number: 220991	File number: E181974	Certificate: CQC15001121716 (DW-16) CQC18001199096 (DWV-8)	Client ID number: 77311

## 6.9 Safety Limiting Values

 Safety limiting<sup>(1)</sup> intends to minimize potential damage to the isolation barrier upon failure of input or output circuitry.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>DW-16 PACKAGE</b>						
I <sub>S</sub>	Safety input, output, or supply current	R <sub>θJA</sub> = 69.9°C/W, V <sub>I</sub> = 5.5 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-1</a>			325	mA
		R <sub>θJA</sub> = 69.9°C/W, V <sub>I</sub> = 3.6 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-1</a>			496	
		R <sub>θJA</sub> = 69.9°C/W, V <sub>I</sub> = 2.75 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-1</a>			650	
		R <sub>θJA</sub> = 69.9°C/W, V <sub>I</sub> = 1.89 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-1</a>			946	
P <sub>S</sub>	Safety input, output, or total power	R <sub>θJA</sub> = 69.9°C/W, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-3</a>			1788	mW
T <sub>S</sub>	Maximum safety temperature				150	°C
<b>DWV-8 PACKAGE</b>						
I <sub>S</sub>	Safety input, output, or supply current	R <sub>θJA</sub> = 100°C/W, V <sub>I</sub> = 5.5 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-2</a>			227	mA
		R <sub>θJA</sub> = 100°C/W, V <sub>I</sub> = 3.6 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-2</a>			347	
		R <sub>θJA</sub> = 100°C/W, V <sub>I</sub> = 2.75 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-2</a>			454	
		R <sub>θJA</sub> = 100°C/W, V <sub>I</sub> = 1.89 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-2</a>			661	
P <sub>S</sub>	Safety input, output, or total power	R <sub>θJA</sub> = 100°C/W, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">图 6-4</a>			1250	mW
T <sub>S</sub>	Maximum safety temperature				150	°C

- (1) The maximum safety temperature, T<sub>S</sub>, has the same value as the maximum junction temperature, T<sub>J</sub>, specified for the device. The I<sub>S</sub> and P<sub>S</sub> parameters represent the safety current and safety power respectively. The maximum limits of I<sub>S</sub> and P<sub>S</sub> should not be exceeded. These limits vary with the ambient temperature, T<sub>A</sub>.



The junction-to-air thermal resistance,  $R_{\theta JA}$ , in the table is that of a device installed on a high-K test board for leaded surface-mount packages. Use these equations to calculate the value for each parameter:

$T_J = T_A + R_{\theta JA} \times P$ , where  $P$  is the power dissipated in the device.

$T_{J(max)} = T_S = T_A + R_{\theta JA} \times P_S$ , where  $T_{J(max)}$  is the maximum allowed junction temperature.

$P_S = I_S \times V_I$ , where  $V_I$  is the maximum input voltage.

## 6.10 Electrical Characteristics - DC Specification

Over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SUPPLY CHARACTERISTICS</b>						
I <sub>CC1</sub>	Supply current Side 1	V <sub>CC1</sub> = 1.71 V to 1.89 V, TXD = 0 V, bus dominant		2.3	3.5	mA
		V <sub>CC1</sub> = 2.25 V to 5.5 V, TXD = 0 V, bus dominant		2.4	3.5	mA
		V <sub>CC1</sub> = 1.71 V to 1.89 V, TXD = V <sub>CC1</sub> , bus recessive		1.2	2.1	mA
		V <sub>CC1</sub> = 2.25 V to 5.5 V, TXD = V <sub>CC1</sub> , bus recessive		1.3	2.1	mA
I <sub>CC2</sub>	Supply current Side 2	TXD = 0 V, bus dominant, R <sub>L</sub> = 60 Ω		43	73.4	mA
		TXD = V <sub>CC1</sub> , bus recessive, R <sub>L</sub> = 60 Ω		2.8	4.1	mA
UV <sub>VCC1</sub>	Rising under voltage detection, Side 1				1.7	V
UV <sub>VCC1</sub>	Falling under voltage detection, Side 1		1.0			V
V <sub>HYS(UVC1)</sub>	Hysteresis voltage on V <sub>CC1</sub> undervoltage lock-out		75	125		mV
UV <sub>VCC2</sub>	Rising under voltage detection, side 2			4.2	4.45	V
UV <sub>VCC2</sub>	Falling under voltage detection, side 2		3.8	4.0	4.25	V
V <sub>HYS(UVC2)</sub>	Hysteresis voltage on V <sub>CC2</sub> undervoltage lock-out			200		mV
<b>TXD TERMINAL</b>						
V <sub>IH</sub>	High level input voltage		0.7×V <sub>CC1</sub>			V
V <sub>IL</sub>	Low level input voltage			0.3×V <sub>CC1</sub>		V
I <sub>IH</sub>	High level input leakage current	TXD = V <sub>CC1</sub>			1	μA
I <sub>IL</sub>	Low level input leakage current	TXD = 0V	-20			μA
C <sub>I</sub>	Input capacitance	V <sub>IN</sub> = 0.4 x sin(2 x π x 1E+6 x t) + 2.5 V, V <sub>CC1</sub> = 5 V		3		pF
<b>RXD TERMINAL</b>						
V <sub>OH</sub> - V <sub>CC1</sub>	High level output voltage	See <a href="#">Fig 7-4</a> , I <sub>O</sub> = -4 mA for 4.5 V ≤ V <sub>CC1</sub> ≤ 5.5 V	-0.4	-0.2		V
		See <a href="#">Fig 7-4</a> , I <sub>O</sub> = -2 mA for 3.0 V ≤ V <sub>CC1</sub> ≤ 3.6 V	-0.2	-0.07		V
		See <a href="#">Fig 7-4</a> , I <sub>O</sub> = -1 mA for 2.25 V ≤ V <sub>CC1</sub> ≤ 2.75 V	-0.1	-0.04		V
		See <a href="#">Fig 7-4</a> , I <sub>O</sub> = -1 mA for 1.71 V ≤ V <sub>CC1</sub> ≤ 1.89 V	-0.1	-0.045		V
V <sub>OL</sub>	Low level output voltage	See <a href="#">Fig 7-4</a> , I <sub>O</sub> = 4 mA for 4.5 V ≤ V <sub>CC1</sub> ≤ 5.5 V		0.2	0.4	V
		See <a href="#">Fig 7-4</a> , I <sub>O</sub> = 2 mA for 3.0 V ≤ V <sub>CC1</sub> ≤ 3.6 V		0.07	0.2	V
		See <a href="#">Fig 7-4</a> , I <sub>O</sub> = 1 mA for 2.25 V ≤ V <sub>CC1</sub> ≤ 2.75 V		0.035	0.1	V
		See <a href="#">Fig 7-4</a> , I <sub>O</sub> = 1 mA for 1.71 V ≤ V <sub>CC1</sub> ≤ 1.89 V		0.04	0.1	V
<b>DRIVER ELECTRICAL CHARACTERISTICS</b>						

Over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>O(DOM)</sub>	Bus output voltage(Dominant), CANH	See 图 7-1 and 图 7-2, TXD = 0 V, 50 Ω ≤ R <sub>L</sub> ≤ 65 Ω, C <sub>L</sub> = open	2.75		4.5	V
	Bus output voltage(Dominant), CANL	See 图 7-1 and 图 7-2, TXD = 0 V, 50 Ω ≤ R <sub>L</sub> ≤ 65 Ω, C <sub>L</sub> = open	0.5		2.25	V
V <sub>O(REC)</sub>	Bus output voltage(recessive), CANH and CANL	See 图 7-1 and 图 7-2, TXD = V <sub>CC1</sub> , R <sub>L</sub> = open	2.0	0.5 x V <sub>CC2</sub>	3.0	V
V <sub>OD(DOM)</sub>	Differential output voltage, CANH-CANL (dominant)	See 图 7-1 and 图 7-2, TXD = 0 V, 45 Ω ≤ R <sub>L</sub> ≤ 50 Ω, C <sub>L</sub> = open	1.4		3.0	V
	Differential output voltage, CANH-CANL (dominant)	See 图 7-1 and 图 7-2, TXD = 0 V, 50 Ω ≤ R <sub>L</sub> ≤ 65 Ω, C <sub>L</sub> = open	1.5		3.0	V
	Differential output voltage, CANH-CANL (dominant)	See 图 7-1 and 图 7-2, TXD = 0 V, R <sub>L</sub> = 2240 Ω, C <sub>L</sub> = open	1.5		5.0	V
V <sub>OD(REC)</sub>	Differential output voltage, CANH-CANL (recessive)	See 图 7-1 and 图 7-2, TXD = V <sub>CC1</sub> , R <sub>L</sub> = 60 Ω, C <sub>L</sub> = open	-120.0		12.0	mV
	Differential output voltage, CANH-CANL (recessive)	See 图 7-1 and 图 7-2, TXD = V <sub>CC1</sub> , R <sub>L</sub> = open, C <sub>L</sub> = open	-50.0		50.0	mV
V <sub>SYM_DC</sub>	DC Output symmetry (V <sub>CC2</sub> - V <sub>O(CANH)</sub> - V <sub>O(CANL)</sub> )	See 图 7-1 and 图 7-2, R <sub>L</sub> = 60 Ω, C <sub>L</sub> = open, TXD = V <sub>CC1</sub> or 0 V	-400.0		400.0	mV
I <sub>SO(SS_DO M)</sub>	Short circuit current steady state output current, dominant	See 图 7-9, V <sub>CANH</sub> = -5 V to 40 V, CANL = open, TXD = 0 V	-100.0			mA
		See 图 7-9, V <sub>CANL</sub> = -5 V to 40 V, CANH = open, TXD = 0 V			100.0	mA
I <sub>SO(SS_RE C)</sub>	Short circuit current steady state output current, recessive	See 图 7-9, -27 V ≤ V <sub>BUS</sub> ≤ 32 V, V <sub>BUS</sub> = CANH = CANL, TXD = V <sub>CC1</sub>	-5.0		5.0	mA
<b>RECEIVER ELECTRICAL CHARACTERISTICS</b>						
V <sub>IT</sub>	Differential input threshold voltage	See 图 7-4 and 表 7-1,  V <sub>CM</sub>   ≤ 20 V	500.0		900.0	mV
	Differential input threshold voltage	See 图 7-4 and 表 7-1, 20 V ≤  V <sub>CM</sub>   ≤ 30 V	400.0		1000.0	
V <sub>HYS</sub>	Hysteresis voltage for differential input threshold	See 图 7-4 and 表 7-1		120		
V <sub>CM</sub>	Input common mode range	See 图 7-4 and 表 7-1	-30.0		30.0	V
I <sub>OFF(LKG)</sub>	Power-off bus input leakage current	CANH = CANL = 5 V, V <sub>CC2</sub> to GND via 0 Ω and 47 k Ω resistor			4.8	uA
C <sub>I</sub>	Input capacitance to ground (CANH or CANL)	TXD = V <sub>CC1</sub>		24.0	30	pF
C <sub>ID</sub>	Differential input capacitance (CANH-CANL)	TXD = V <sub>CC1</sub>		12.0	15	pF
R <sub>ID</sub>	Differential input resistance	TXD = V <sub>CC1</sub> ; -30 V ≤ V <sub>CM</sub> ≤ +30 V	30.0		80.0	k Ω
R <sub>IN</sub>	Input resistance (CANH or CANL)	TXD = V <sub>CC1</sub> ; -30 V ≤ V <sub>CM</sub> ≤ +30 V	15.0		40.0	k Ω
R <sub>IN(M)</sub>	Input resistance matching: (1 - R <sub>IN(CANH)</sub> /R <sub>IN(CANL)</sub> ) x 100%	V <sub>CANH</sub> = V <sub>CANL</sub> = 5 V	-2.0		2.0	%
<b>THERMAL SHUTDOWN</b>						
T <sub>TSD</sub>	Thermal shutdown temperature			170		°C
T <sub>TSD_HYS T</sub>	Thermal shutdown hysteresis			5		°C

## 6.11 Switching Characteristics

Over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>DEVICE SWITCHING CHARACTERISTICS</b>						
t <sub>PROP(LOOP1)</sub>	Total loop delay, driver input TXD to receiver RXD, recessive to dominant	See <a href="#">Fig 7-6</a> , R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns; 1.71 V ≤ V <sub>CC1</sub> ≤ 1.89 V	70	125	198.0	ns
		See <a href="#">Fig 7-6</a> , R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns; 2.25 V ≤ V <sub>CC1</sub> ≤ 5.5 V	70	122	192.0	ns
t <sub>PROP(LOOP2)</sub>	Total loop delay, driver input TXD to receiver RXD, dominant to recessive	See <a href="#">Fig 7-6</a> , R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns; 1.71 V ≤ V <sub>CC1</sub> ≤ 1.89 V	70	155	215.0	ns
		See <a href="#">Fig 7-6</a> , R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns; 2.25 V ≤ V <sub>CC1</sub> ≤ 5.5 V	70	152	215.0	ns
t <sub>UV_REENABLE</sub>	Re-enable time after Undervoltage event	Time for device to return to normal operation from V <sub>CC1</sub> or V <sub>CC2</sub> under voltage event			300.0	μs
CMTI	Common mode transient immunity	V <sub>CM</sub> = 1200 V <sub>PK</sub> , See <a href="#">Fig 7-10</a>	85	100		kV/μs
<b>DRIVER SWITCHING CHARACTERISTICS</b>						
t <sub>pHR</sub>	Propagation delay time, HIGH TXD to driver recessive	See <a href="#">Fig 7-3</a> , R <sub>L</sub> = 60 Ω and C <sub>L</sub> = 100 pF; input rise/fall time (10% to 90%) on TXD = 1 ns		76	120	ns
t <sub>pLD</sub>	Propagation delay time, LOW TXD to driver dominant			61	120	
t <sub>sk(p)</sub>	Pulse skew ( t <sub>pHR</sub> - t <sub>pLD</sub>  )			14		
t <sub>R</sub>	Differential output signal rise time			45		
t <sub>F</sub>	Differential output signal fall time			45		
V <sub>SYM</sub>	Output symmetry (dominant or recessive) (V <sub>O(CANH)</sub> + V <sub>O(CANL)</sub> ) / V <sub>CC2</sub>	See <a href="#">Fig 7-3</a> and <a href="#">Fig 9-4</a> , R <sub>TERM</sub> = 60 Ω, C <sub>SPLIT</sub> = 4.7 nF, C <sub>L</sub> = open, R <sub>L</sub> = open, TXD = 250 kHz, 1 MHz	0.9		1.1	V/V
t <sub>TXD_DTO</sub>	Dominant time out	See <a href="#">Fig 7-8</a> , R <sub>L</sub> = 60 Ω and C <sub>L</sub> = open	1.2		3.8	ms
<b>RECEIVER SWITCHING CHARACTERISTICS</b>						
t <sub>pRH</sub>	Propagation delay time, bus recessive input to RXD high output	See <a href="#">Fig 7-5</a> , C <sub>L(RXD)</sub> = 15 pF		75	130	ns
t <sub>pDL</sub>	Propagation delay time, bus dominant input to RXD low output			63	130	ns
t <sub>R</sub>	Output signal rise time(RXD)			1.4		ns
t <sub>F</sub>	Output signal fall time(RXD)			1.8		ns
<b>FD TIMING PARAMETERS</b>						
t <sub>BIT(BUS)</sub>	Bit time on CAN bus output pins with t <sub>BIT(TXD)</sub> = 500 ns	See <a href="#">Fig 7-7</a> , R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns	435.0		530.0	ns
	Bit time on CAN bus output pins with t <sub>BIT(TXD)</sub> = 200 ns	See <a href="#">Fig 7-7</a> , R <sub>L</sub> = 60 Ω, C <sub>L</sub> = 100 pF, C <sub>L(RXD)</sub> = 15 pF; input rise/fall time (10% to 90%) on TXD = 1 ns	155.0		210.0	ns

Over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{\text{BIT(RXD)}}$	Bit time on RXD output pins with $t_{\text{BIT(TXD)}} = 500 \text{ ns}$	See 图 7-7, $R_L = 60 \Omega$ , $C_L = 100 \text{ pF}$ , $C_{L(\text{RXD})} = 15 \text{ pF}$ ; input rise/fall time (10% to 90%) on TXD = 1 ns	400		550.0	ns
	Bit time on RXD output pins with $t_{\text{BIT(TXD)}} = 200 \text{ ns}$	See 图 7-7, $R_L = 60 \Omega$ , $C_L = 100 \text{ pF}$ , $C_{L(\text{RXD})} = 15 \text{ pF}$ ; input rise/fall time (10% to 90%) on TXD = 1 ns	120.0		220.0	ns
$\Delta t_{\text{REC}}$	Receiver timing symmetry with $t_{\text{BIT(TXD)}} = 500 \text{ ns}$	See 图 7-7, $R_L = 60 \Omega$ , $C_L = 100 \text{ pF}$ , $C_{L(\text{RXD})} = 15 \text{ pF}$ ; input rise/fall time (10% to 90%) on TXD = 1 ns; $\Delta t_{\text{REC}} = t_{\text{BIT(RXD)}} - t_{\text{BIT(BUS)}}$	-65.0		40.0	ns
	Receiver timing symmetry with $t_{\text{BIT(TXD)}} = 200 \text{ ns}$	See 图 7-7, $R_L = 60 \Omega$ , $C_L = 100 \text{ pF}$ , $C_{L(\text{RXD})} = 15 \text{ pF}$ ; input rise/fall time (10% to 90%) on TXD = 1 ns; $\Delta t_{\text{REC}} = t_{\text{BIT(RXD)}} - t_{\text{BIT(BUS)}}$	-45.0		15.0	ns

## 6.12 Insulation Characteristics Curves

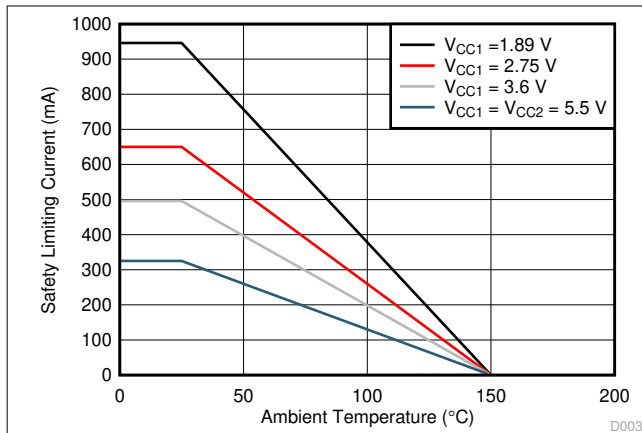


图 6-1. Thermal Derating Curve for Limiting Current per VDE for DW-16 Package

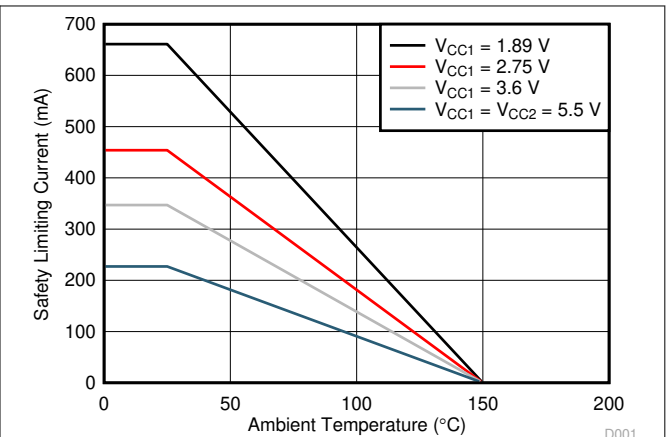


图 6-2. Thermal Derating Curve for Limiting Current per VDE for DWV-8 Package

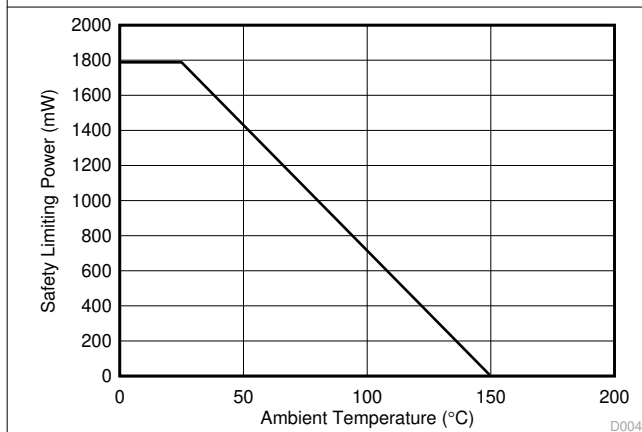


图 6-3. Thermal Derating Curve for Limiting Power per VDE for DW-16 Package

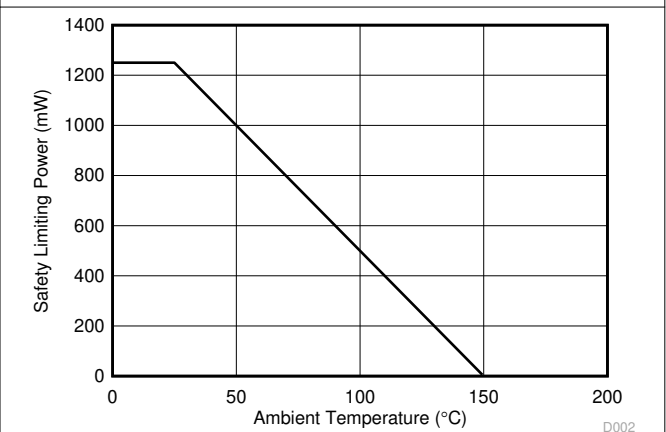


图 6-4. Thermal Derating Curve for Limiting Power per VDE for DWV-8 Package

### 6.13 Typical Characteristics

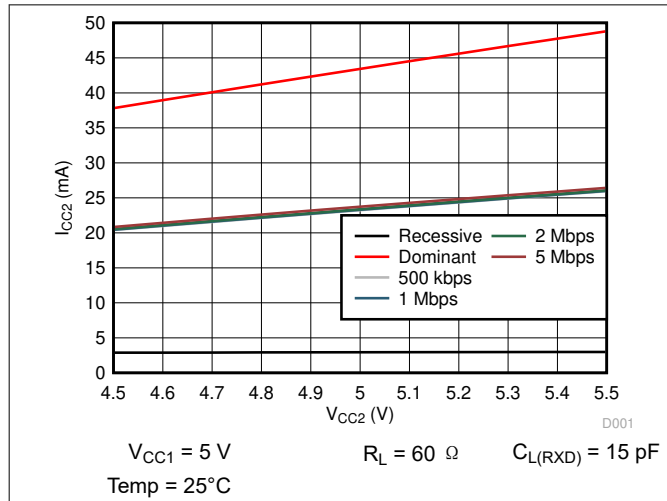


图 6-5.  $I_{CC2}$  vs  $V_{CC2}$  for Recessive, Dominant and Different CAN Datarates

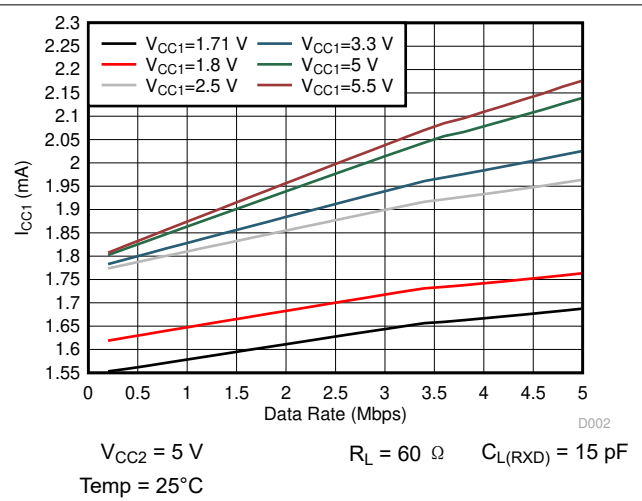


图 6-6.  $I_{CC1}$  vs Datarate

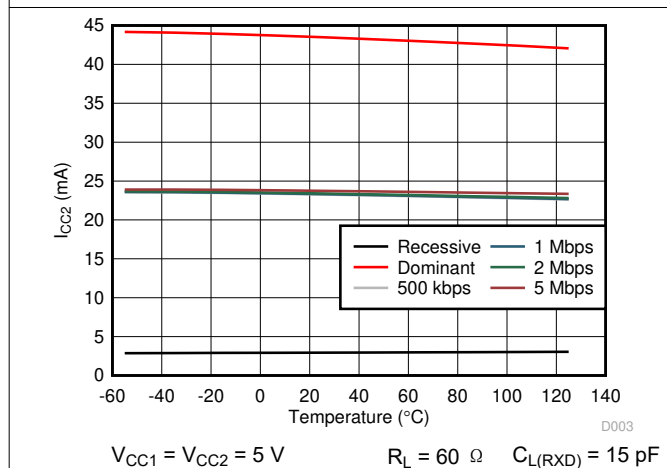


图 6-7.  $I_{CC2}$  vs Ambient Temperature for Recessive, Dominant and Different CAN Datarates

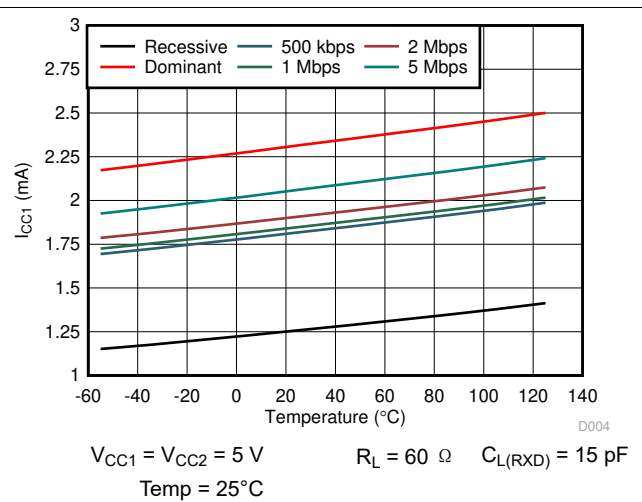


图 6-8. :  $I_{CC1}$  vs Ambient Temperature for Recessive, Dominant and Different CAN Datarates.

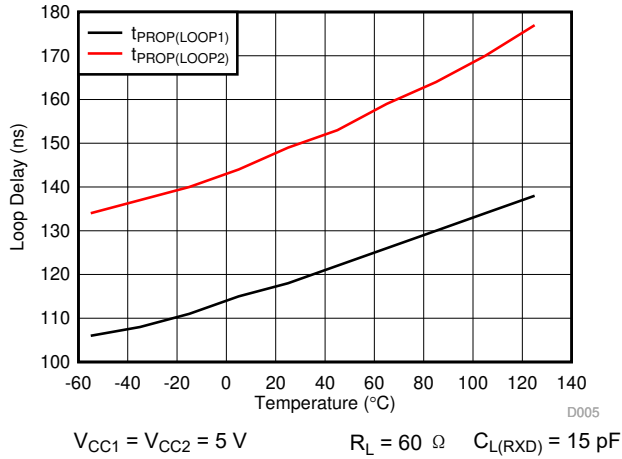


图 6-9. Loop Delay vs Ambient Temperature

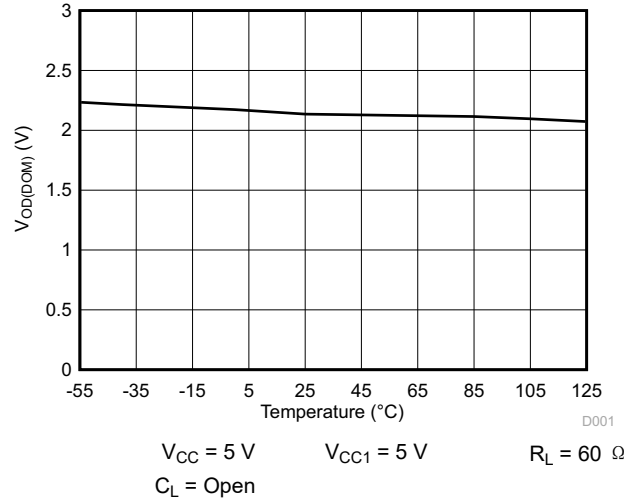


图 6-10.  $V_{OD(DOM)}$  Over Temperature

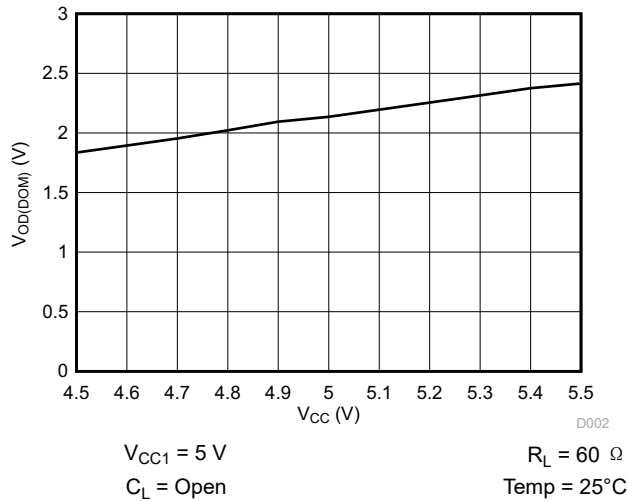


图 6-11.  $V_{OD(DOM)}$  Over  $V_{CC}$

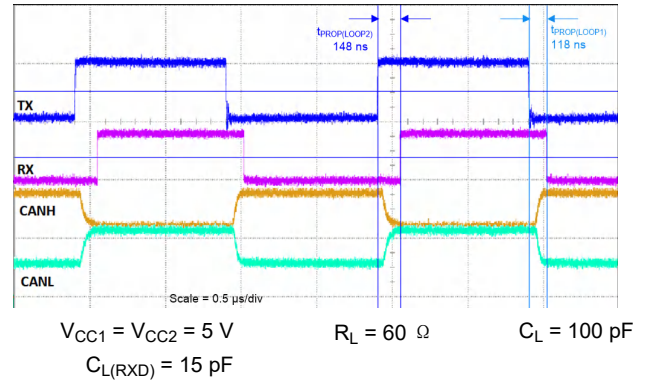


图 6-12. Typical TXD, RXD, CANH and CANL Waveforms at 1 Mbps

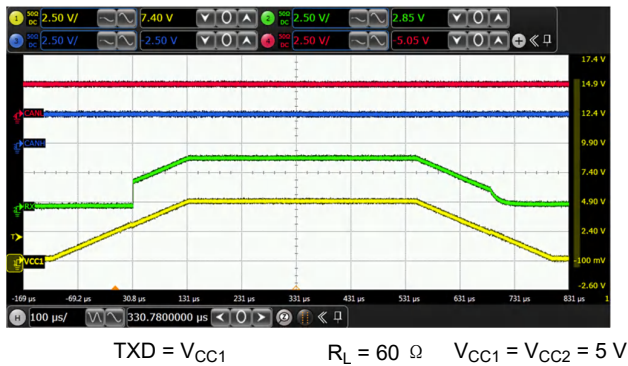


图 6-13. Glitch Free Power Up on  $V_{CC1}$  - CAN Bus Remains Recessive

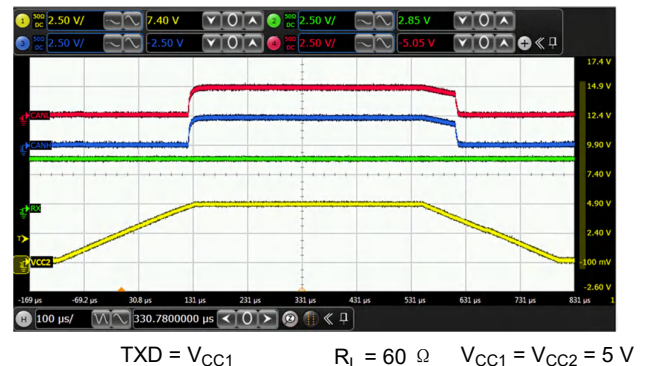


图 6-14. Glitch Free Power Up on  $V_{CC2}$  - CAN Bus Remains Recessive

## 7 Parameter Measurement Information

### 7.1 Test Circuits

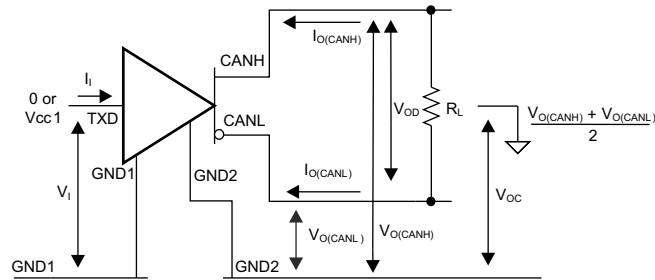


图 7-1. Driver Voltage, Current and Test Definitions

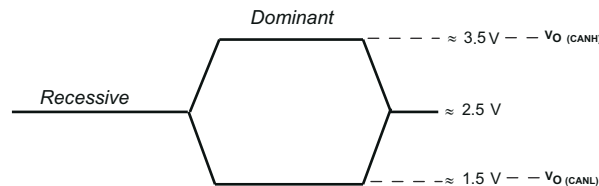
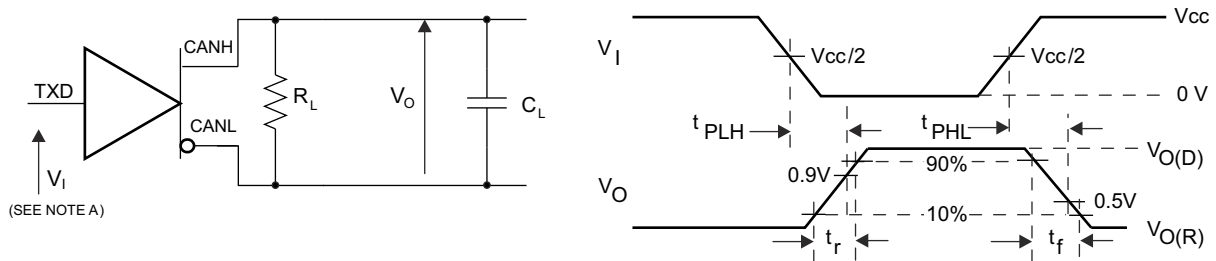


图 7-2. Bus Logic State Voltage Definitions



- A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  125 kHz, 50% duty cycle,  $t_r \leq$  6 ns,  $t_f \leq$  6 ns,  $Z_O = 50 \Omega$ .

图 7-3. Driver Test Circuit and Voltage Waveforms

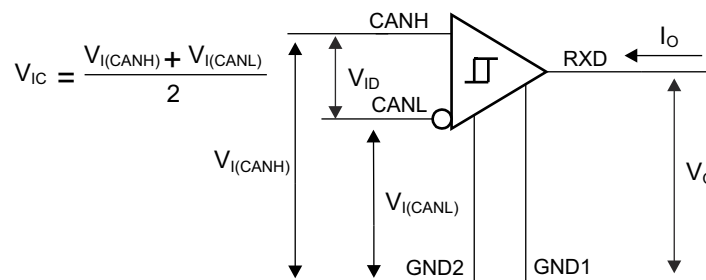
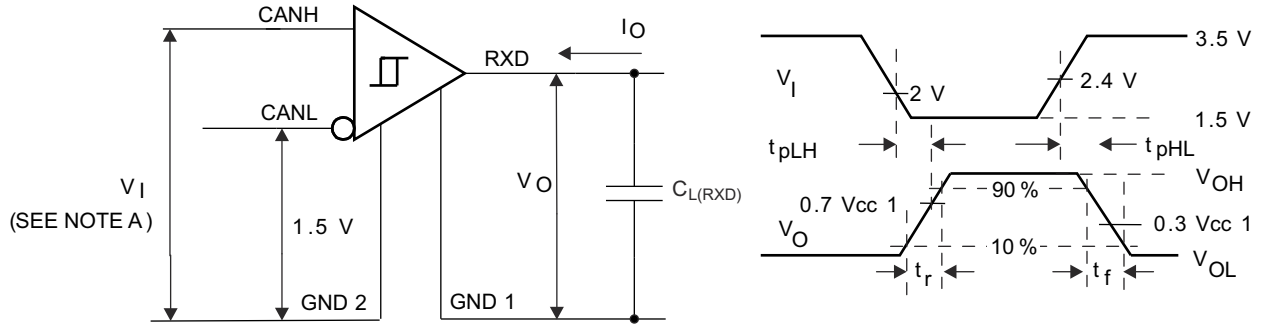


图 7-4. Receiver Voltage and Current Definitions





- A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  125 kHz, 50% duty cycle,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_0 = 50 \Omega$ .

图 7-5. Receiver Test Circuit and Voltage Waveforms

表 7-1. Receiver Differential Input Voltage Threshold Test

INPUT			OUTPUT	
$V_{CANH}$	$V_{CANL}$	$ V_{ID} $	RXD	
-29.5 V	-30.5 V	1000 mV	L	$V_{OL}$
30.5 V	29.5 V	1000 mV	L	
-19.55 V	-20.45 V	900 mV	L	
20.45 V	19.55 V	900 mV	L	
-19.75 V	-20.25 V	500 mV	H	$V_{OH}$
20.25 V	19.75 V	500 mV	H	
-29.8 V	-30.2 V	400 mV	H	
30.2 V	29.8 V	400 mV	H	
Open	Open	X	H	

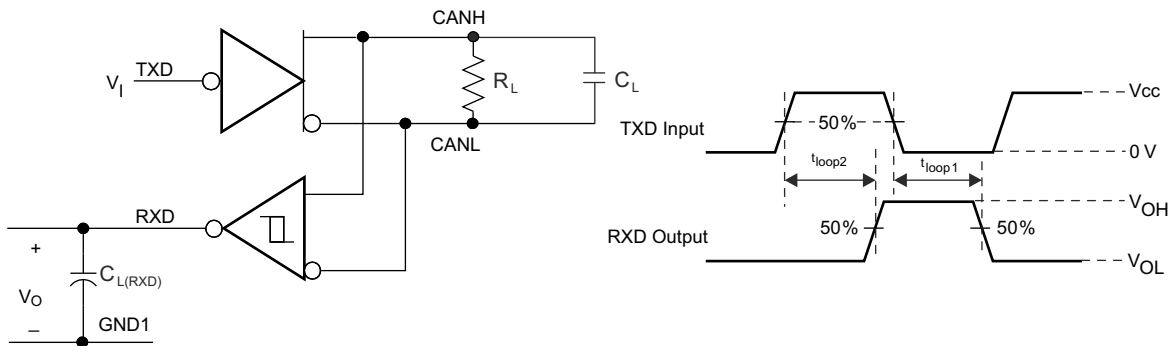


图 7-6.  $t_{LOOP}$  Test Circuit and Voltage Waveforms

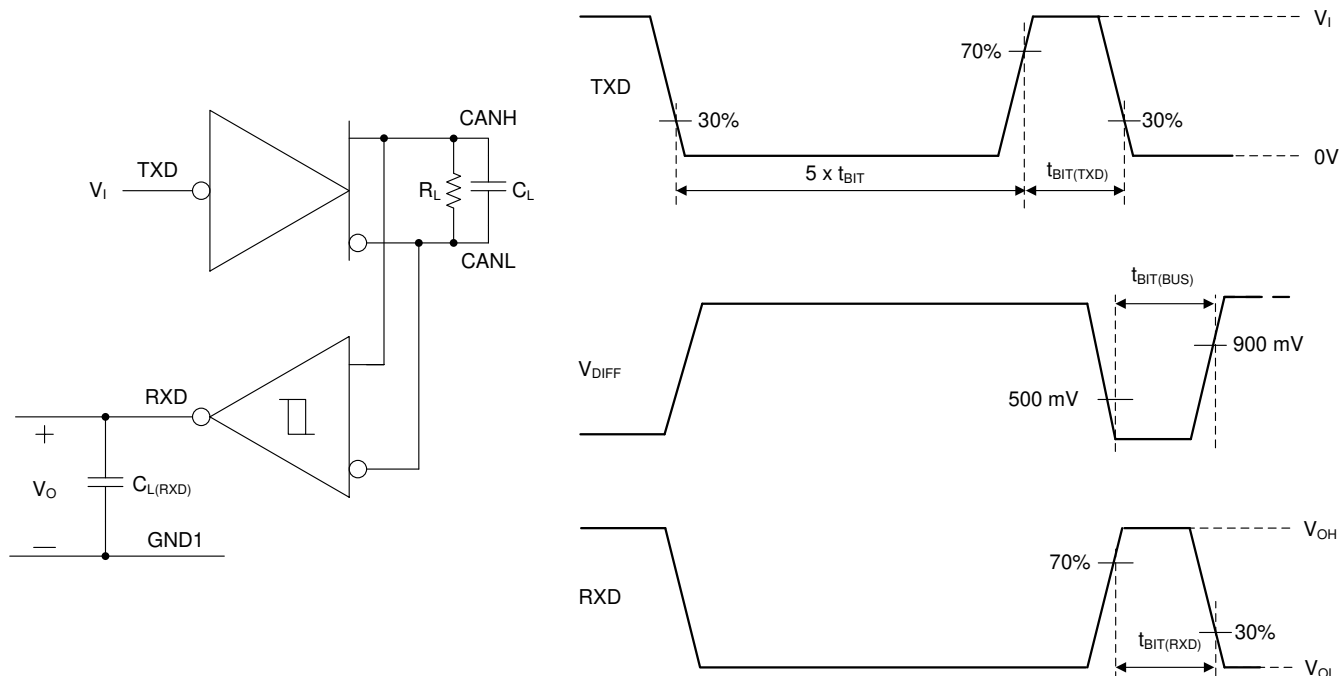
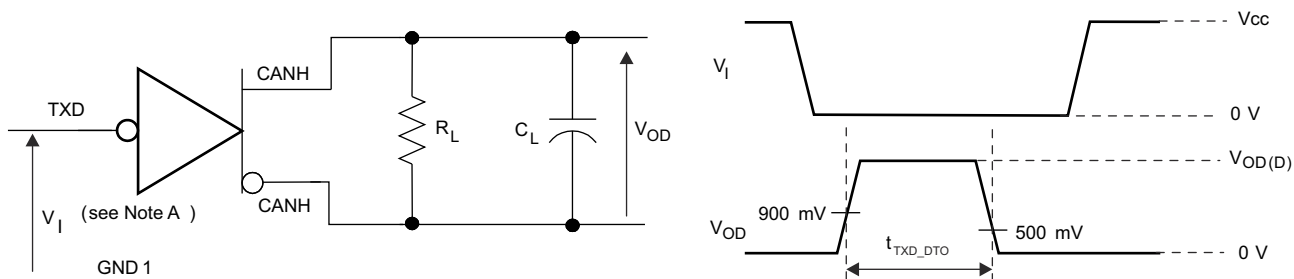


图 7-7. CAN FD Timing Parameter Measurement



A. The input pulse is supplied by a generator having the following characteristics:  $t_r \leq 6 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$ ,  $Z_0 = 50 \Omega$ .

图 7-8. Dominant Time-out Test Circuit and Voltage Waveforms

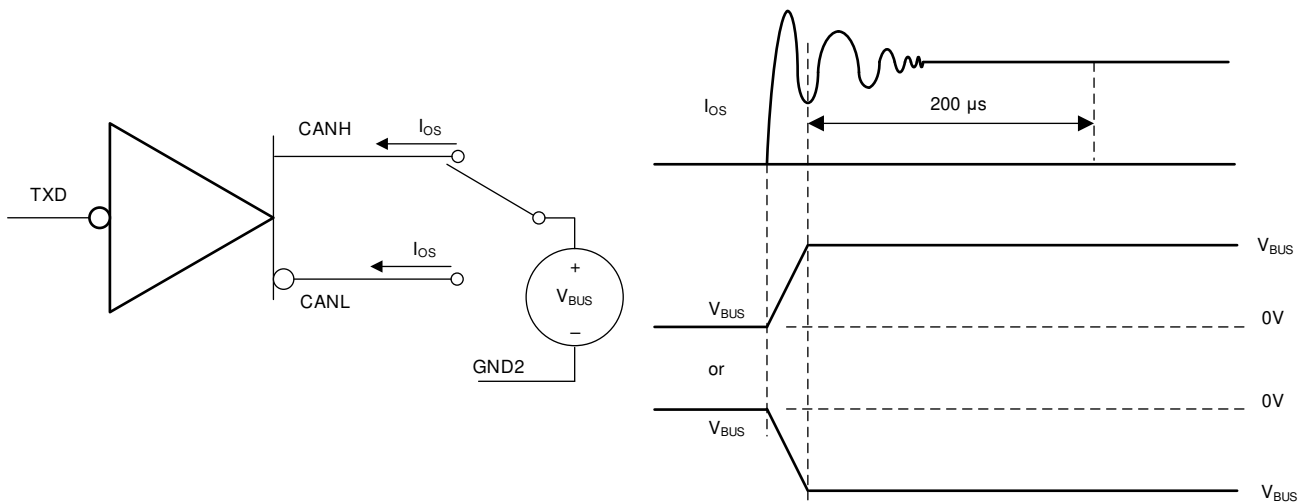


图 7-9. Driver Short-Circuit Current Test Circuit and Waveforms

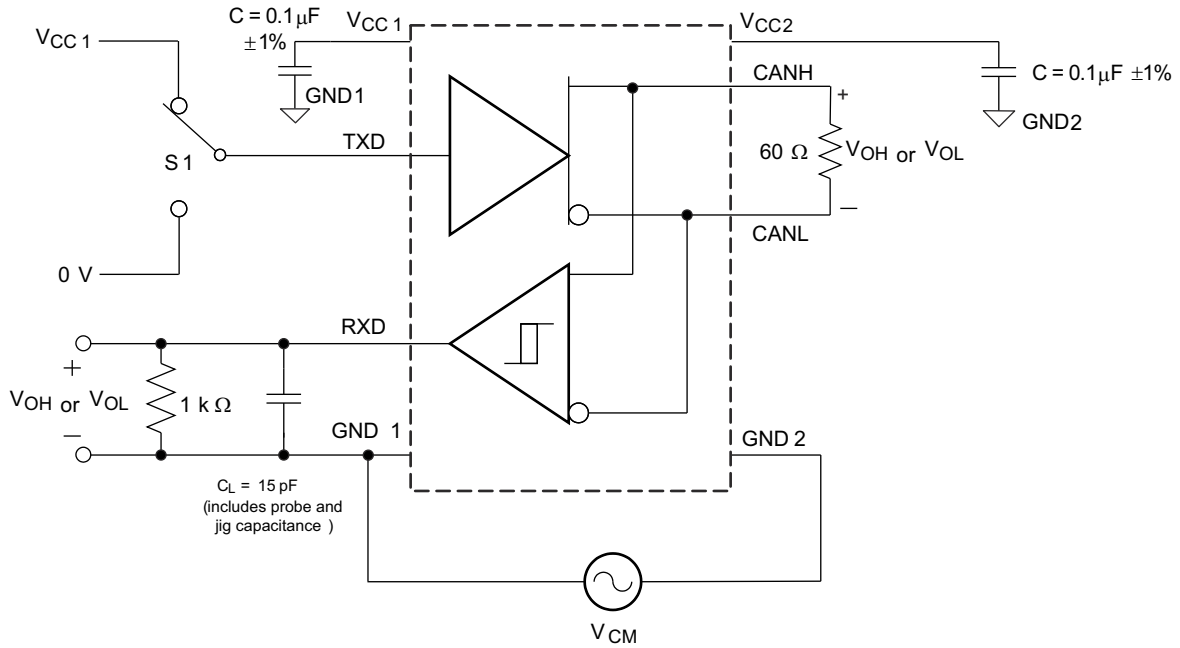


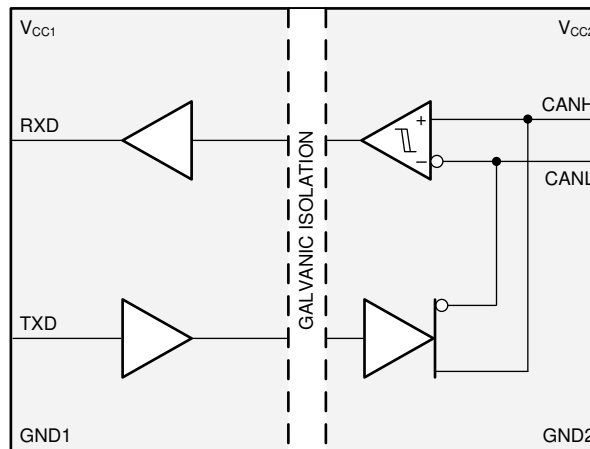
图 7-10. Common-Mode Transient Immunity Test Circuit

## 8 Detailed Description

### 8.1 Overview

The ISO1042-Q1 device is a digitally isolated CAN transceiver that offers  $\pm 70$ -V DC bus fault protection and  $\pm 30$ -V common-mode voltage range. The device supports up to 5-Mbps data rate in CAN FD mode allowing much faster transfer of payload compared to classic CAN. The ISO1042-Q1 device has an isolation withstand voltage of  $5000 V_{RMS}$  and is available in basic and reinforced isolation with a surge test voltage of  $6 kV_{PK}$  and  $10 kV_{PK}$  respectively. The device can operate from 1.8-V, 2.5-V, 3.3-V, and 5-V supplies on side 1 and a 5-V supply on side 2. This supply range is of particular advantage for applications operating in harsh industrial environments because the low voltage on side 1 enables the connection to low-voltage microcontrollers for power conservation, whereas the 5 V on side 2 maintains a high signal-to-noise ratio of the bus signals.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

#### 8.3.1 CAN Bus States

The CAN bus has two states during operation: *dominant* and *recessive*. A dominant bus state, equivalent to logic low, is when the bus is driven differentially by a driver. A recessive bus state is when the bus is biased to a common mode of  $V_{CC} / 2$  through the high-resistance internal input resistors of the receiver, equivalent to a logic high. The host microprocessor of the CAN node uses the TXD pin to drive the bus and receives data from the bus on the RXD pin. See [Figure 8-1](#) and [Figure 8-2](#).

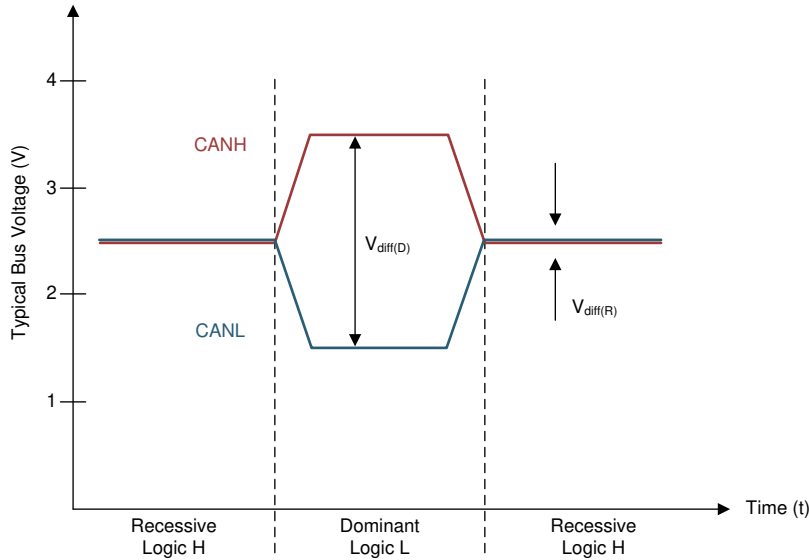


图 8-1. Bus States (Physical Bit Representation)

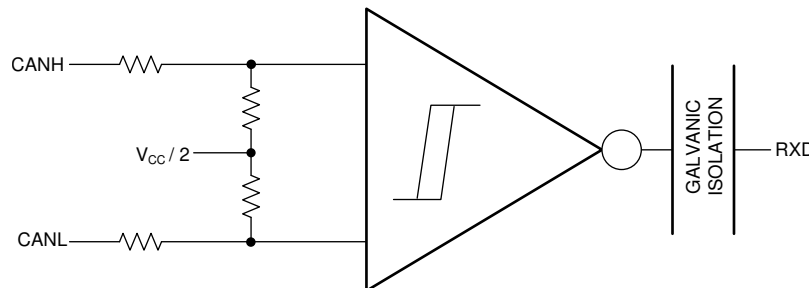


图 8-2. Simplified Recessive Common Mode Bias and Receiver

### 8.3.2 Digital Inputs and Outputs: TXD (Input) and RXD (Output)

The  $V_{CC1}$  supply for the isolated digital input and output side of the device can be supplied by 1.8-V, 2.5-V, 3.3-V, and 5-V supplies and therefore the digital inputs and outputs are 1.8-V, 2.5-V, 3.3-V, and 5-V compatible.

#### 备注

The TXD pin is very weakly internally pulled up to  $V_{CC1}$ . An external pullup resistor should be used to make sure that the TXD pin is biased to recessive (high) level to avoid issues on the bus if the microprocessor does not control the pin and the TXD pin floats. The TXD pullup strength and CAN bit timing require special consideration when the device is used with an open-drain TXD output on the CAN controller of the microprocessor. An adequate external pullup resistor must be used to make sure that the TXD output of the microprocessor maintains adequate bit timing input to the input on the transceiver.

### 8.3.3 Protection Features

#### 8.3.3.1 TXD Dominant Timeout (DTO)

The TXD DTO circuit prevents the transceiver from blocking network communication in the event of a hardware or software failure where the TXD pin is held dominant longer than the timeout period,  $t_{TXD\_DTO}$ . The DTO circuit timer starts on a falling edge on the TXD pin. The DTO circuit disables the CAN bus driver if no rising edge occurs before the timeout period expires, which frees the bus for communication between other nodes on the network. The CAN driver is activated again when a recessive signal occurs on the TXD pin, clearing the TXD

DTO condition. The receiver and RXD pin still reflect activity on the CAN bus, and the bus terminals are biased to the recessive level during a TXD dominant timeout.

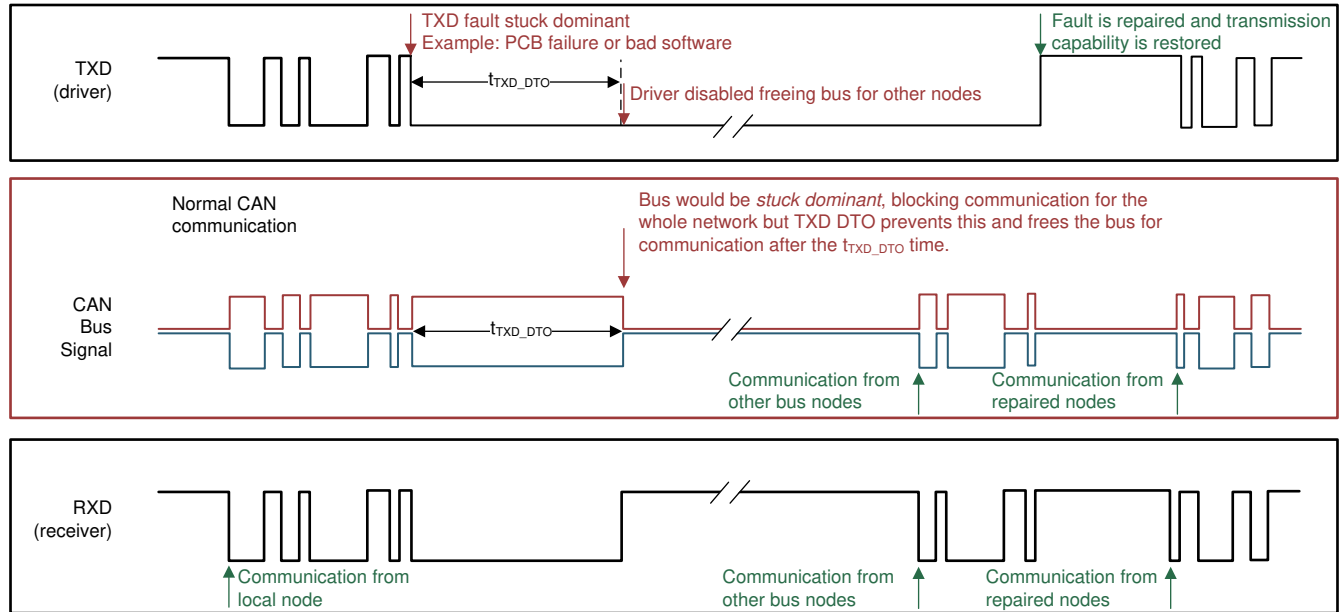


图 8-3. Example Timing Diagram for TXD DTO

备注

The minimum dominant TXD time ( $t_{TXD\_DTO}$ ) allowed by the TXD DTO circuit limits the minimum possible transmitted data rate of the device. The CAN protocol allows a maximum of eleven successive dominant bits (on TXD) for the worst case, where five successive dominant bits are followed immediately by an error frame. This, along with the  $t_{TXD\_DTO}$  minimum, limits the minimum data rate. Calculate the minimum transmitted data rate with [方程式 1](#).

$$\text{Minimum Data Rate} = 11 / t_{TXD\_DTO} \tag{1}$$

**8.3.3.2 Thermal Shutdown (TSD)**

If the junction temperature of the device exceeds the thermal shutdown threshold ( $T_{TSD}$ ), the device turns off the CAN driver circuits, blocking the TXD-to-bus transmission path. The CAN bus terminals are biased to the recessive level during a thermal shutdown, and the receiver-to-RXD path remains operational. The shutdown condition is cleared when the junction temperature drops at least the thermal shutdown hysteresis temperature ( $T_{TSD\_HYST}$ ) below the thermal shutdown temperature ( $T_{TSD}$ ) of the device.

**8.3.3.3 Undervoltage Lockout and Default State**

The supply pins have undervoltage detection that places the device in protected or default mode which protects the bus during an undervoltage event on the  $V_{CC1}$  or  $V_{CC2}$  supply pins. If the bus-side power supply,  $V_{CC2}$ , is less than about 4 V, the power shutdown circuits in the ISO1042-Q1 device disable the transceiver to prevent false transmissions because of an unstable supply. If the  $V_{CC1}$  supply is still active when this occurs, the receiver output (RXD) goes to a default HIGH (recessive) value. [表 8-1](#) summarizes the undervoltage lockout and fail-safe behavior.

表 8-1. Undervoltage Lockout and Default State

$V_{CC1}$	$V_{CC2}$	DEVICE STATE	BUS OUTPUT	RXD
$> UV_{VCC1}$	$> UV_{VCC2}$	Functional	Per Device State and TXD	Mirrors Bus
$< UV_{VCC1}$	$> UV_{VCC2}$	Protected	Recessive	Undetermined

**表 8-1. Undervoltage Lockout and Default State (continued)**

$V_{CC1}$	$V_{CC2}$	DEVICE STATE	BUS OUTPUT	RXD
$>UV_{VCC1}$	$<UV_{VCC2}$	Protected	High Impedance	Recessive (Default High)

**备注**

After an undervoltage condition is cleared and the supplies have returned to valid levels, the device typically resumes normal operation in 300  $\mu$ s.

**8.3.3.4 Floating Pins**

Pullup and pulldown resistors should be used on critical pins to place the device into known states if the pins float. The TXD pin should be pulled up through a resistor to the  $V_{CC1}$  pin to force a recessive input level if the microprocessor output to the pin floats.

**8.3.3.5 Unpowered Device**

The device is designed to be *ideal passive* or *no load* to the CAN bus if it is unpowered. The bus pins (CANH, CANL) have extremely low leakage currents when the device is unpowered to avoid loading down the bus which is critical if some nodes of the network are unpowered while the rest of the network remains in operation.

**8.3.3.6 CAN Bus Short Circuit Current Limiting**

The device has two protection features that limit the short circuit current when a CAN bus line has a short-circuit fault condition. The first protection feature is driver current limiting (both dominant and recessive states) and the second feature is TXD dominant state time out to prevent permanent higher short circuit current of the dominant state during a system fault. During CAN communication the bus switches between dominant and recessive states, therefore the short circuit current may be viewed either as the instantaneous current during each bus state or as an average current of the two states. For system current (power supply) and power considerations in the termination resistors and common-mode choke ratings, use the average short circuit current. Determine the ratio of dominant and recessive bits by the data in the CAN frame plus the following factors of the protocol and PHY that force either recessive or dominant at certain times:

- Control fields with set bits
- Bit stuffing
- Interframe space
- TXD dominant time out (fault case limiting)

These factors ensure a minimum recessive amount of time on the bus even if the data field contains a high percentage of dominant bits. The short circuit current of the bus depends on the ratio of recessive to dominant bits and their respective short circuit currents. Use [方程式 2](#) to calculate the average short circuit current.

$$I_{OS(AVG)} = \%Transmit \times [(\%REC\_Bits \times I_{OS(SS)\_REC}) + (\%DOM\_Bits \times I_{OS(SS)\_DOM})] + [\%Receive \times I_{OS(SS)\_REC}] \quad (2)$$

where

- $I_{OS(AVG)}$  is the average short circuit current
- $\%Transmit$  is the percentage the node is transmitting CAN messages
- $\%Receive$  is the percentage the node is receiving CAN messages
- $\%REC\_Bits$  is the percentage of recessive bits in the transmitted CAN messages
- $\%DOM\_Bits$  is the percentage of dominant bits in the transmitted CAN messages
- $I_{OS(SS)\_REC}$  is the recessive steady state short circuit current
- $I_{OS(SS)\_DOM}$  is the dominant steady state short circuit current

## 备注

Consider the short circuit current and possible fault cases of the network when sizing the power ratings of the termination resistance and other network components.

## 8.4 Device Functional Modes

表 8-2 和 表 8-3 list the driver and receiver functions. 表 8-4 lists the functional modes for the ISO1042-Q1 device.

表 8-2. Driver Function Table

INPUT	OUTPUTS		DRIVEN BUS STATE
	TXD <sup>(1)</sup>	CANH <sup>(1)</sup>	
L	H	L	Dominant
H	Z	Z	Recessive

(1) H = high level, L = low level, Z = common mode (recessive) bias to  $V_{CC} / 2$ . See 图 8-1 and 图 8-2 for bus state and common mode bias information.

表 8-3. Receiver Function Table

DEVICE MODE	CAN DIFFERENTIAL INPUTS $V_{ID} = V_{CANH} - V_{CANL}$ <sup>(3)</sup>	BUS STATE	RXD PIN <sup>(1)</sup>
Normal	$V_{ID} \geq V_{IT(MAX)}$	Dominant	L
	$V_{IT(MIN)} < V_{ID} < V_{IT(MAX)}$	?	?
	$V_{ID} \leq V_{IT(MIN)}$	Recessive	H
	Open ( $V_{ID} \approx 0$ V)	Open	H

(1) H = high level, L = low level, ? = indeterminate.

表 8-4. Function Table

DRIVER			RECEIVER			
INPUTS <sup>(1)</sup>	OUTPUTS		BUS STATE	DIFFERENTIAL INPUTS $V_{ID} = CANH - CANL$ <sup>(3)</sup>	OUTPUT RXD	BUS STATE
	TXD	CANH				
L <sup>(2)</sup>	H	L	DOMINANT	$V_{ID} \geq V_{IT(MAX)}$	L	DOMINANT
H	Z	Z	RECESSIVE	$V_{IT(MIN)} < V_{ID} < V_{IT(MAX)}$	?	?
Open	Z	Z	RECESSIVE	$V_{ID} \leq V_{IT(MIN)}$	H	RECESSIVE
X	Z	Z	RECESSIVE	Open ( $V_{ID} \approx 0$ V)	H	RECESSIVE

(1) H = high level; L = low level; X = irrelevant; ? = indeterminate; Z = high impedance

(2) Logic low pulses to prevent dominant time-out.

(3) See Receiver Electrical Characteristics section for input thresholds.



## 9 Application and Implementation

### 备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The ISO1042-Q1 device can be used with other components from Texas Instruments such as a microcontroller, a transformer driver, and a linear voltage regulator to form a fully isolated CAN interface.

### 9.2 Typical Application

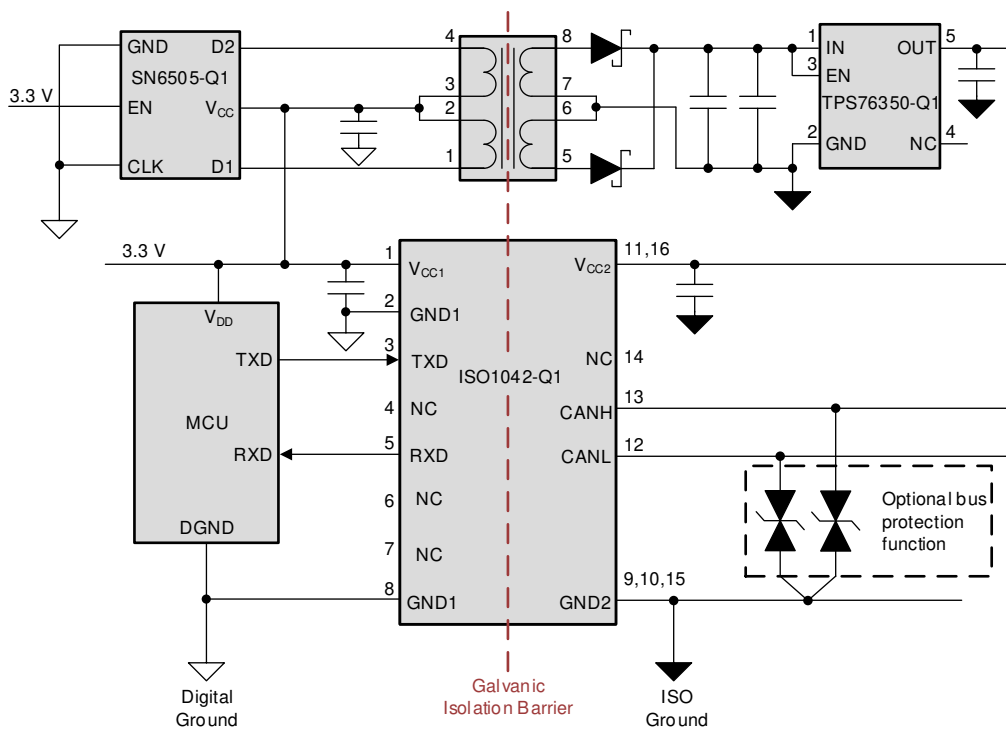


图 9-1. Application Circuit With ISO1042-Q1 in 16-SOIC Package



to terminate both ends of the cable to prevent signal reflections. Unterminated drop-lines (stubs) connecting nodes to the bus should be kept as short as possible to minimize signal reflections. The termination may be in a node, but if nodes are removed from the bus, the termination must be carefully placed so that it is not removed from the bus.

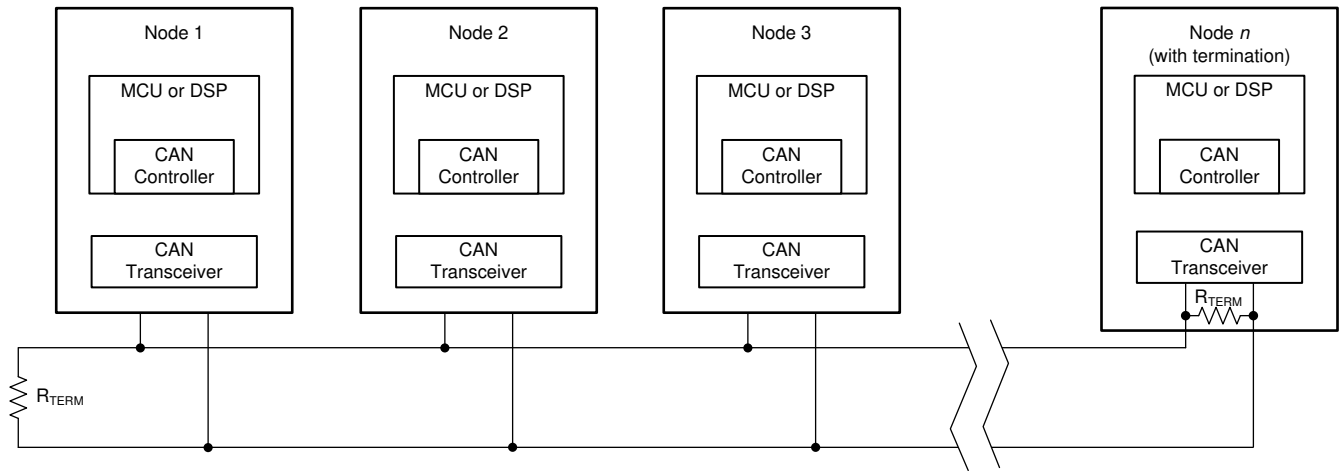


图 9-3. Typical CAN Bus

Termination may be a single 120-Ω resistor at the end of the bus, either on the cable or in a terminating node. If filtering and stabilization of the common-mode voltage of the bus is desired, then split termination can be used. (See 图 9-4). Split termination improves the electromagnetic emissions behavior of the network by eliminating fluctuations in the bus common-mode voltages at the start and end of message transmissions.

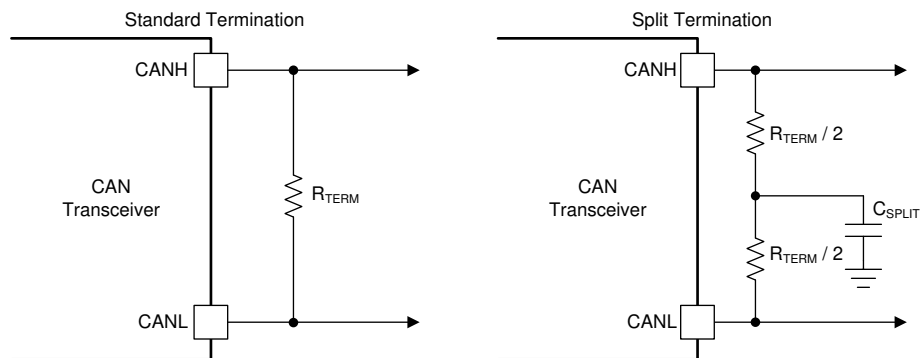


图 9-4. CAN Bus Termination Concepts

### 9.2.3 Application Curve

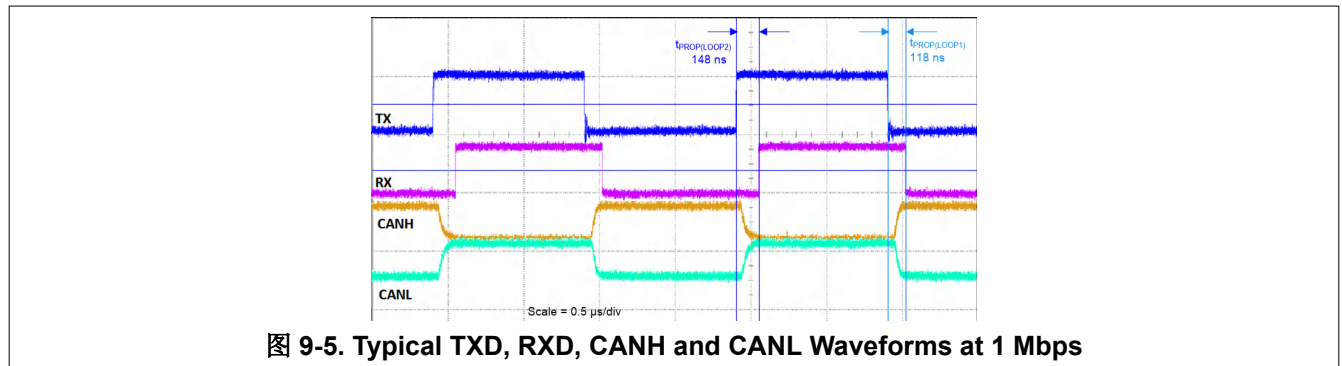


图 9-5. Typical TXD, RXD, CANH and CANL Waveforms at 1 Mbps

## 10 Power Supply Recommendations

To make sure operation is reliable at all data rates and supply voltages, a 0.1- $\mu$ F bypass capacitor is recommended at the input and output supply pins ( $V_{CC1}$  and  $V_{CC2}$ ). The capacitors should be placed as close to the supply pins as possible. In addition, a bulk capacitance, typically 4.7  $\mu$ F, should be placed near the  $V_{CC2}$  supply pin. If only a single primary-side power supply is available in an application, isolated power can be generated for the secondary-side with the help of a transformer driver such as TI's [SN6505B](#). For such applications, detailed power supply design, and transformer selection recommendations are available in the [SN6505 Low-Noise 1-A Transformer Drivers for Isolated Power Supplies data sheet](#).

## 11 Layout

### 11.1 Layout Guidelines

A minimum of four layers is required to accomplish a low EMI PCB design (see 节 11.2). Layer stacking should be in the following order (top-to-bottom): high-speed signal layer, ground plane, power plane and low-frequency signal layer.

- Routing the high-speed traces on the top layer avoids the use of vias (and the introduction of their inductances) and allows for clean interconnects between the isolator and the transmitter and receiver circuits of the data link.
- Placing a solid ground plane next to the high-speed signal layer establishes controlled impedance for transmission line interconnects and provides an excellent low-inductance path for the return current flow.
- Placing the power plane next to the ground plane creates additional high-frequency bypass capacitance of approximately 100 pF/in<sup>2</sup>.
- Routing the slower speed control signals on the bottom layer allows for greater flexibility as these signal links usually have margin to tolerate discontinuities such as vias.

Suggested placement and routing of ISO1042-Q1 bypass capacitors and optional TVS diodes is shown in 图 11-2 and 图 11-3. In particular, place the  $V_{CC2}$  bypass capacitors on the top layer, as close to the device pins as possible, and complete the connection to the  $V_{CC2}$  and  $G_{ND2}$  pins without using vias. Note that the SOIC-16 variant needs two  $V_{CC2}$  bypass capacitor, one on each  $V_{CC2}$  pin.

If an additional supply voltage plane or signal layer is needed, add a second power or ground plane system to the stack to keep it symmetrical. This makes the stack mechanically stable and prevents it from warping. Also the power and ground plane of each power system can be placed closer together, thus increasing the high-frequency bypass capacitance significantly.

For detailed layout recommendations, refer to the [Digital Isolator Design Guide](#).

#### 11.1.1 PCB Material

For digital circuit boards operating at less than 150 Mbps, (or rise and fall times greater than 1 ns), and trace lengths of up to 10 inches, use standard FR-4 UL94V-0 printed circuit board. This PCB is preferred over lower-cost alternatives because of lower dielectric losses at high frequencies, less moisture absorption, greater strength and stiffness, and the self-extinguishing flammability-characteristics.

### 11.2 Layout Example

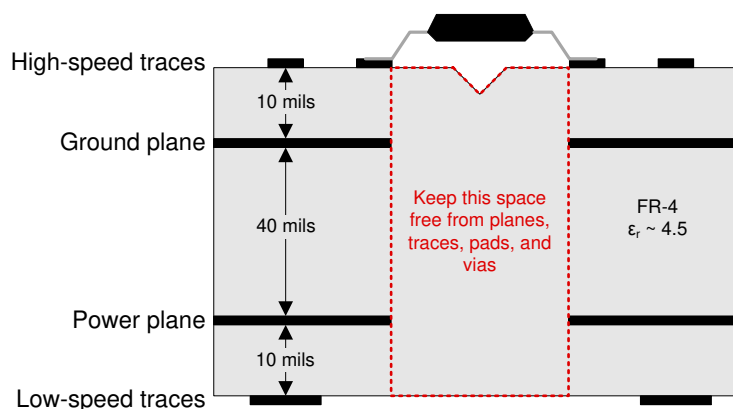


图 11-1. Recommended Layer Stack

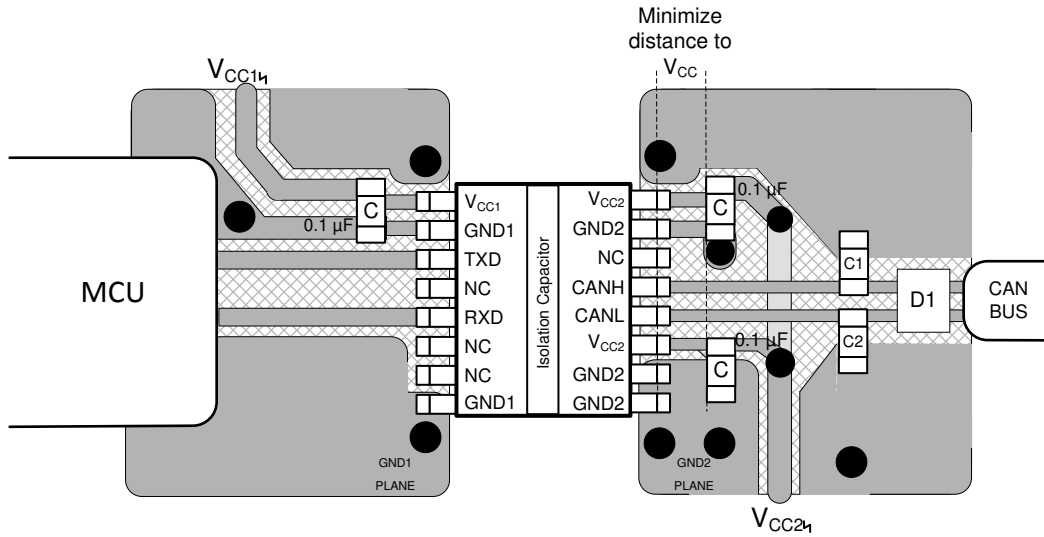


图 11-2. 16-DW Layout Example

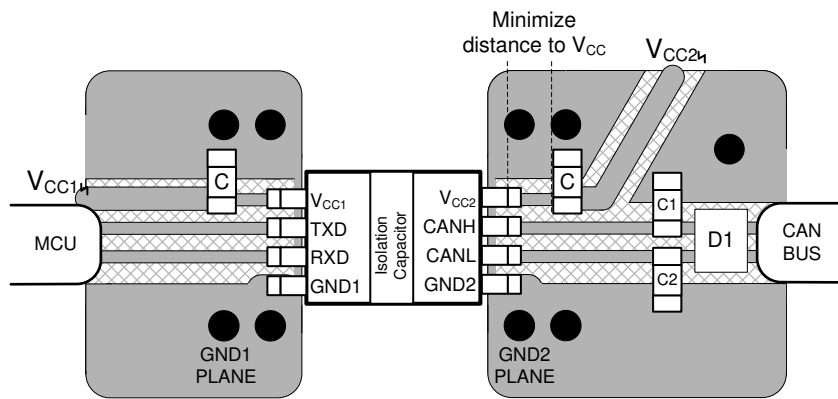


图 11-3. 8-DWV Layout Example

## 12 Device and Documentation Support

### 12.1 Documentation Support

#### 12.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [Digital Isolator Design Guide](#)
- Texas Instruments, [ISO1042DW Isolated CAN Transceiver Evaluation Module User's Guide](#)
- Texas Instruments, [Isolate your CAN systems without compromising on performance or space TI TechNote](#)
- Texas Instruments, [Isolation Glossary](#)
- Texas Instruments, [High-voltage reinforced isolation: Definitions and test methodologies](#)
- Texas Instruments, [How to Isolate Signal and Power in Isolated CAN Systems TI TechNote](#)
- Texas Instruments, [How to Design Isolated CAN Systems With Correct Bus Protection Application Report](#)

#### 12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

#### 12.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

#### 12.4 Trademarks

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#### 12.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

#### 12.6 术语表

TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ISO1042BQDWQ1	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISO1042BQ1	<a href="#">Samples</a>
ISO1042BQDWRQ1	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISO1042BQ1	<a href="#">Samples</a>
ISO1042BQDWVQ1	ACTIVE	SOIC	DWV	8	64	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISO1042B Q1	<a href="#">Samples</a>
ISO1042BQDWRVQ1	ACTIVE	SOIC	DWV	8	1000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISO1042B Q1	<a href="#">Samples</a>
ISO1042QDWQ1	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISO1042Q1	<a href="#">Samples</a>
ISO1042QDWRQ1	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISO1042Q1	<a href="#">Samples</a>
ISO1042QDWVQ1	ACTIVE	SOIC	DWV	8	64	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISO1042 Q1	<a href="#">Samples</a>
ISO1042QDWRVQ1	ACTIVE	SOIC	DWV	8	1000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISO1042 Q1	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO1042BQDWRQ1	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1042BQDWVRQ1	SOIC	DWV	8	1000	330.0	16.4	12.05	6.15	3.3	16.0	16.0	Q1
ISO1042QDWRQ1	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
ISO1042QDWVRQ1	SOIC	DWV	8	1000	330.0	16.4	12.05	6.15	3.3	16.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ISO1042BQDWRQ1	SOIC	DW	16	2000	350.0	350.0	43.0
ISO1042BQDWVRQ1	SOIC	DWV	8	1000	350.0	350.0	43.0
ISO1042QDWRQ1	SOIC	DW	16	2000	350.0	350.0	43.0
ISO1042QDWVRQ1	SOIC	DWV	8	1000	350.0	350.0	43.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
ISO1042BQDWQ1	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1042BQDWVQ1	DWV	SOIC	8	64	505.46	13.94	4826	6.6
ISO1042QDWQ1	DW	SOIC	16	40	506.98	12.7	4826	6.6
ISO1042QDWVQ1	DWV	SOIC	8	64	505.46	13.94	4826	6.6

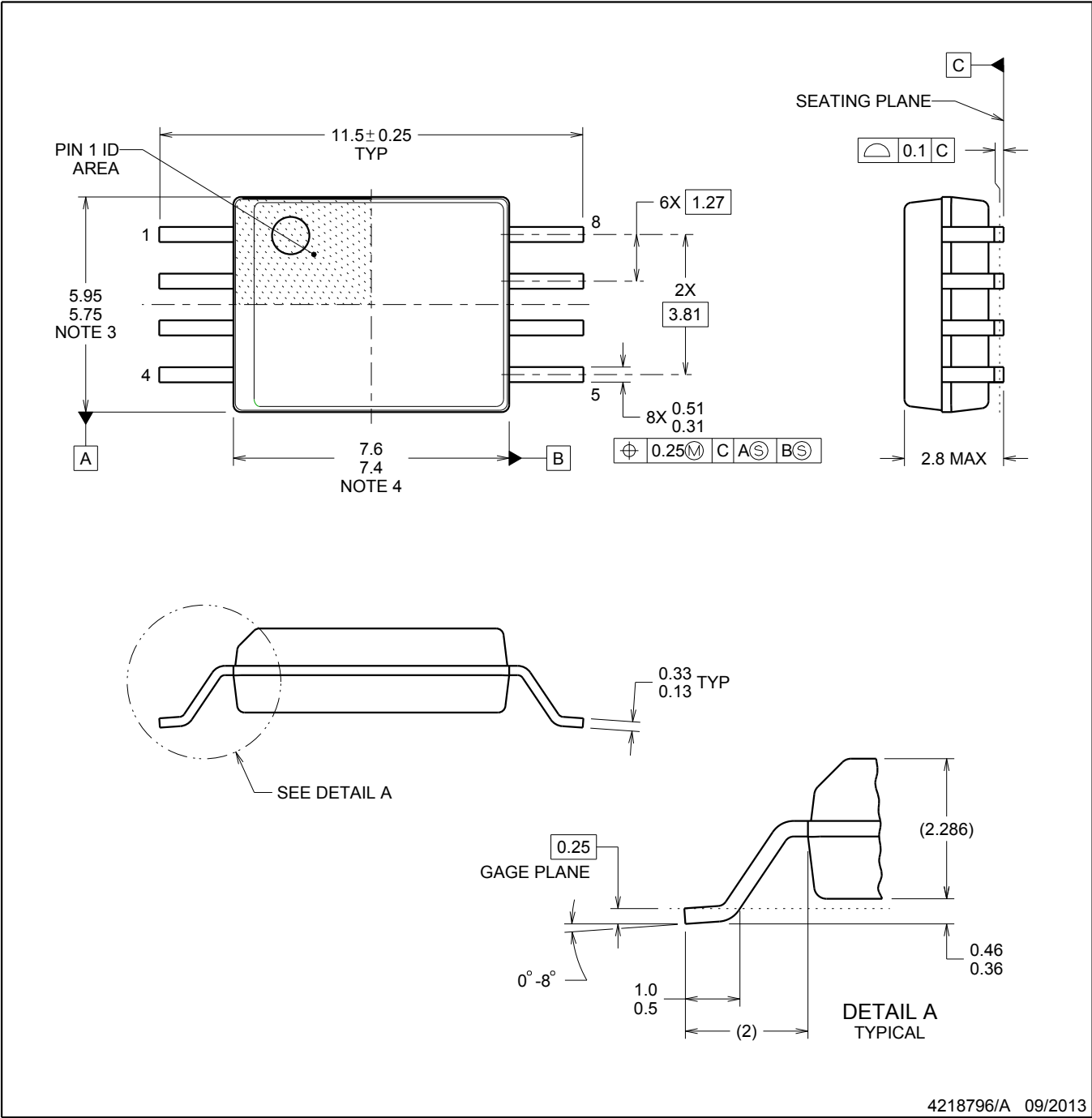
# PACKAGE OUTLINE

DWV0008A



SOIC - 2.8 mm max height

SOIC



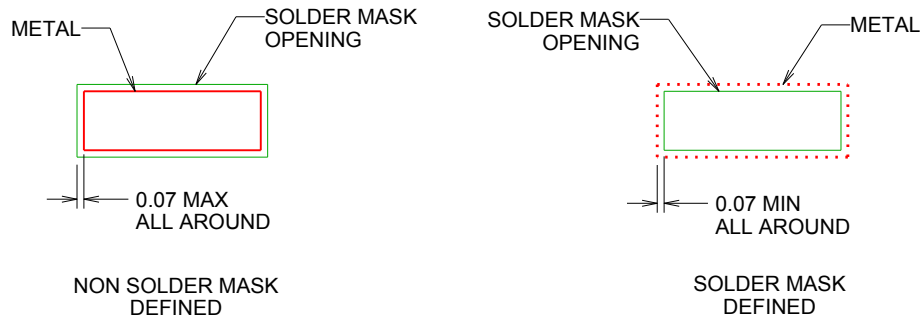
4218796/A 09/2013

**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE  
9.1 mm NOMINAL CLEARANCE/CREEPAGE  
SCALE:6X

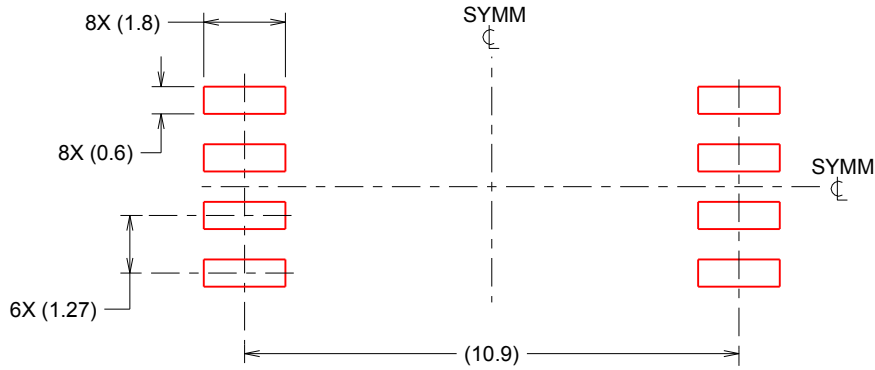


SOLDER MASK DETAILS

4218796/A 09/2013

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL  
 SCALE:6X

4218796/A 09/2013

NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**DW 16**

**SOIC - 2.65 mm max height**

7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4224780/A

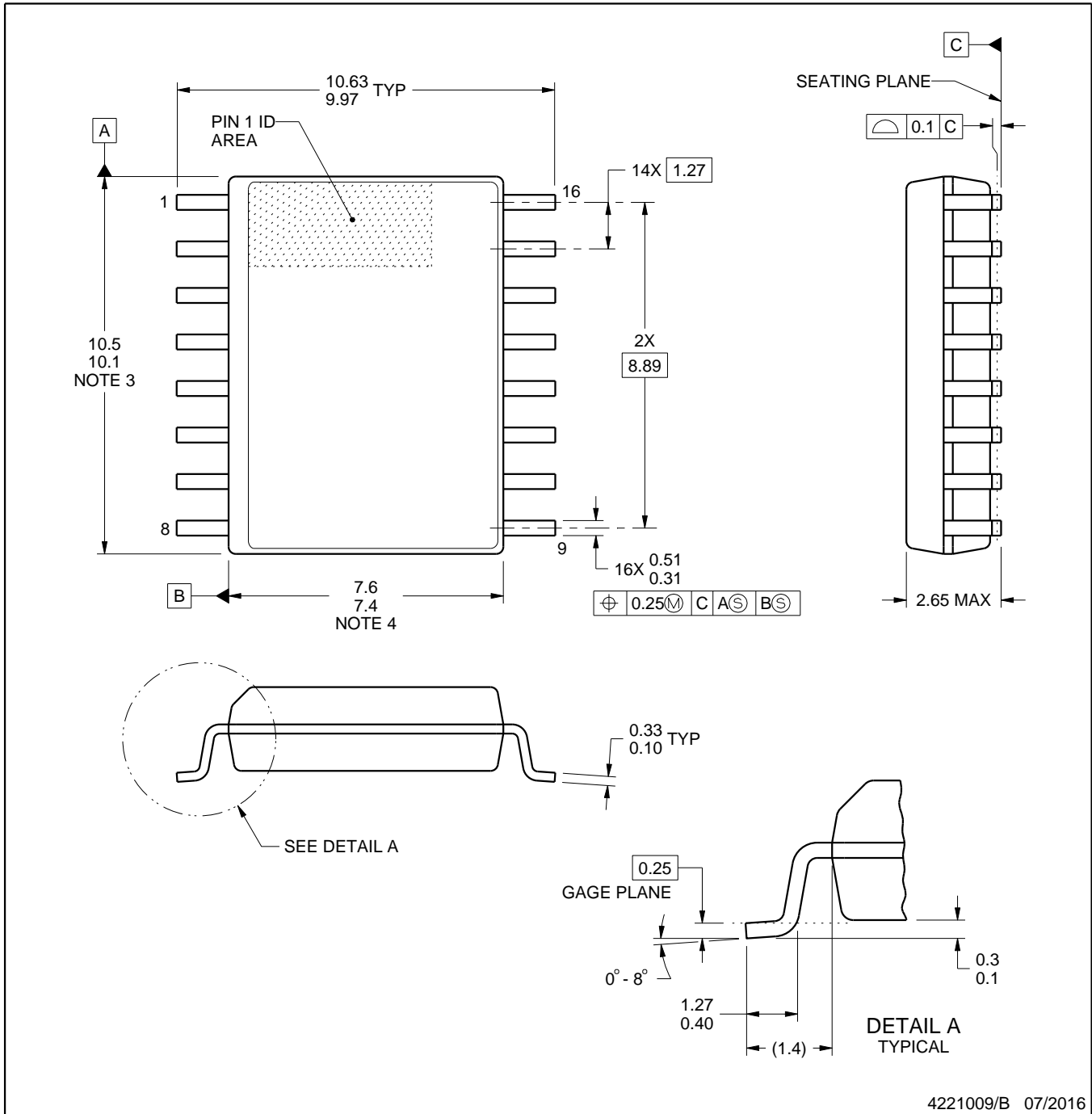




# DW0016B

# PACKAGE OUTLINE SOIC - 2.65 mm max height

SOIC



4221009/B 07/2016

### NOTES:

- All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
- Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

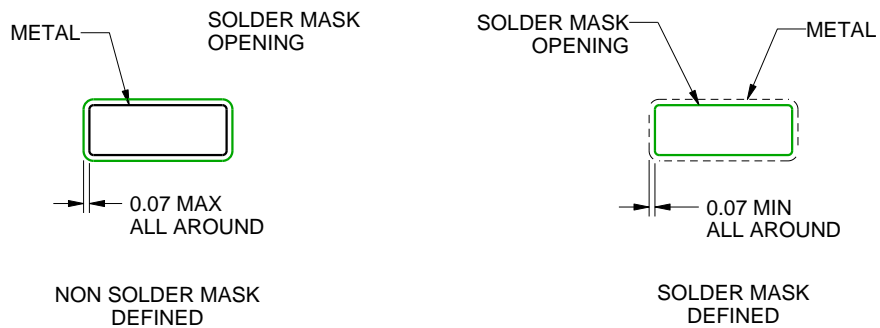
DW0016B

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:4X



SOLDER MASK DETAILS

4221009/B 07/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0016B

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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